

TPS74701 プログラマブル・ソフトスタート機能付き、500mA 低ドロップアウト・リニア・レギュレータ

1 特長

- V_{OUT} 範囲: 0.8V~3.6V
- 非常に低い V_{IN} 範囲: 0.8V~5.5V
- V_{BIAS} 範囲: 2.7V~5.5V
- 低いドロップアウト:
 - 50mV (500mA 時の代表値、 $V_{BIAS} = 5V$)
- パワー・グッド (PG) 出力により、電源電圧の監視、他の電源へのシーケンシング信号の供給が可能
- 入力電圧、負荷、温度に関する精度: 2%
- プログラム可能なソフトスタートにより、直線的に電圧が立ち上がるようにスタートアップさせることが可能
- V_{BIAS} により、優れた過渡応答の低 V_{IN} 動作を実現
- 任意の出力コンデンサ ($\geq 2.2\mu F$) で安定に動作
- 3mm × 3mm × 1mm の小型 10 ピン・パッケージで供給

2 アプリケーション

- ネットワーク接続ストレージ (NAS) - エンタープライズ
- ラック・サーバー
- ネットワーク・インターフェイス・カード (NIC)
- 商用ネットワークとサーバーの PSU (電源)

3 概要

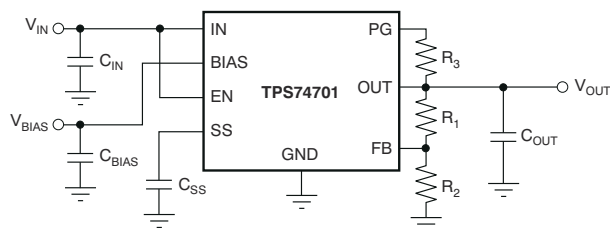
TPS74701 低ドロップアウト (LDO) リニア・レギュレータは、広範なアプリケーション向けの使いやすく堅牢なパワー・マネージメント・ソリューションです。ソフトスタートをユーザーがプログラムできるので、スタートアップ時の容量性突入電流を低減して、入力電源のストレスを最小限に抑えることができます。ソフトスタートは単調性で、多くの種類のプロセッサおよび特定用途向け IC (ASIC) の電源供給に適しています。イネーブル入力とパワー・グッド出力により、外部レギュレータとの間でシーケンシングを簡単に実行できます。このような高い柔軟性により、FPGA や DSP、その他の特殊なスタートアップ条件を持つアプリケーションのシーケンス制御条件を満たすソリューションを構成できます。

高精度の基準電圧およびエラー・アンプは、負荷、ライン、温度、プロセスの範囲全体にわたって 2% の精度を維持します。本デバイスは 2.2 μF 以上の任意のタイプのコンデンサで安定して動作し、-40°C~+125°C で仕様が規定されています。TPS74701 は、小型の 3mm × 3mm VSON-10 パッケージで供給されるため、TPS74801 との互換性があります。

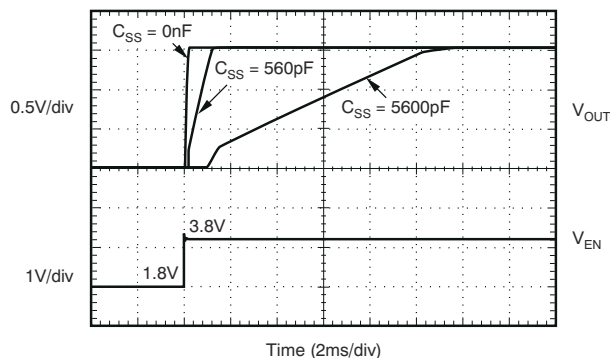
パッケージ情報

部品番号	パッケージ ⁽¹⁾	本体サイズ (公称)
TPS74701	DRC (VSON, 10)	3.00mm × 3.00mm

- (1) 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。



代表的なアプリケーション回路 (可変)



ターンオン応答



Table of Contents

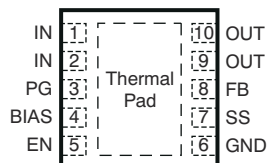
1 特長	1	7 Detailed Description	17
2 アプリケーション	1	7.1 Overview.....	17
3 概要	1	7.2 Functional Block Diagram.....	17
4 Revision History	2	7.3 Feature Description.....	18
5 Pin Configuration and Functions	3	7.4 Device Functional Modes.....	20
6 Specifications	4	8 Application and Implementation	21
6.1 Absolute Maximum Ratings.....	4	8.1 Application Information.....	21
6.2 ESD Ratings.....	4	8.2 Typical Application.....	24
6.3 Recommended Operating Conditions.....	4	8.3 Power Supply Recommendations.....	25
6.4 Thermal Information.....	5	8.4 Layout.....	25
6.5 Electrical Characteristics: Other Orderable Devices (non-M3 Suffix).....	6	9 Device and Documentation Support	29
6.6 Electrical Characteristics: Orderable Device (M3 Suffix).....	7	9.1 Device Support.....	29
6.7 Typical Characteristics: $V_{EN} = V_{IN}$ (All Other Orderable Devices, Non-M3 Suffix).....	8	9.2 Documentation Support.....	29
6.8 Typical Characteristics: $V_{EN} = V_{IN} = 1.8\text{ V}$, V_{OUT} $= 1.5\text{ V}$ (All Other Orderable Devices, Non-M3 Suffix).....	11	9.3 ドキュメントの更新通知を受け取る方法.....	29
6.9 Typical Characteristics: $I_{OUT} = 50\text{ mA}$ (M3 Suffix)....	12	9.4 サポート・リソース.....	29
6.10 Typical Characteristics: $V_{EN} = V_{IN} = 1.8\text{ V}$, V_{OUT} $= 1.5\text{ V}$ (M3 Suffix).....	16	9.5 Trademarks.....	29
		9.6 静電気放電に関する注意事項.....	29
		9.7 用語集.....	30
		10 Mechanical, Packaging, and Orderable Information	30

4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision G (September 2015) to Revision H (April 2023)	Page
• 文書全体にわたって表、図、相互参照の採番方法を更新	1
• ドキュメント全体で SON を VSON に変更.....	1
• ドキュメントに M3 サフィックス・デバイスを追加.....	1
• Added M3-suffix <i>Typical Characteristics</i> sections.....	12
Changes from Revision F (November 2010) to Revision G (September 2015)	Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。	1

5 Pin Configuration and Functions



 **5-1. DRC Package, 10-Pin VSON (Top View)**

表 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
IN	1, 2	I	Input to the device.
EN	5	I	Enable pin. Driving this pin high enables the regulator. Driving this pin low puts the regulator into shutdown mode. This pin must not be left unconnected.
SS	7	—	Soft-start pin. A capacitor connected on this pin to ground sets the start-up time. If this pin is left unconnected, the regulator output soft-start ramp time is typically 200 μ s.
BIAS	4	I	Bias input voltage for error amplifier, reference, and internal control circuits.
PG	3	O	Power-good pin. An open-drain, active-high output that indicates the status of V_{OUT} . When V_{OUT} exceeds the PG trip threshold, the PG pin goes into a high-impedance state. When V_{OUT} is below this threshold the pin is driven to a low-impedance state. A pullup resistor from 10 k Ω to 1 M Ω must be connected from this pin to a supply of up to 5.5 V. The supply can be higher than the input voltage. Alternatively, the PG pin can be left unconnected if output monitoring is not necessary.
FB	8	I	Feedback pin. The feedback connection to the center tap of an external resistor divider network that sets the output voltage. This pin must not be left floating.
OUT	9, 10	O	Regulated output voltage. A small capacitor (total typical capacitance $\geq 2.2 \mu$ F, ceramic) is needed from this pin to ground to assure stability.
NC	N/A	I	No connection. This pin can be left floating or connected to GND to allow better thermal contact to the top-side plane.
GND	6	I	Ground
Thermal Pad	—	I	Solder this pad to the ground plane for increased thermal performance.

6 Specifications

6.1 Absolute Maximum Ratings

over operating temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{IN} , V_{BIAS}	Input voltage	-0.3	6	V
V_{EN}	Enable voltage	-0.3	6	V
V_{PG}	Power good voltage	-0.3	6	V
I_{PG}	PG sink current	0	1.5	mA
V_{SS}	Soft-start voltage	-0.3	6	V
V_{FB}	Feedback voltage	-0.3	6	V
V_{OUT}	Output voltage	-0.3	$V_{IN} + 0.3$	V
I_{OUT}	Maximum output current	Internally limited		
	Output short-circuit duration	Indefinite		
P_{DISS}	Continuous total power dissipation	See Thermal Information		
T_J	Junction Temperature	-40	150	°C
T_{stg}	Storage Temperature	-55	150	

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{IN}	Input supply voltage	$V_{OUT} + V_{DO}$ (V_{IN})	$V_{OUT} + 0.3$	5.5	V
V_{EN}	Enable supply voltage	0	V_{IN}	5.5	V
V_{BIAS} ⁽¹⁾	BIAS supply voltage	$V_{OUT} + V_{DO}$ (V_{BIAS}) ⁽²⁾	$V_{OUT} + 1.4$ ⁽²⁾	5.5	V
V_{OUT}	Output voltage	0.8		3.3	V
I_{OUT}	Output current	0		500	mA
C_{OUT}	Output capacitor	2.2			μF
C_{IN}	Input capacitor ⁽³⁾	1			μF
C_{BIAS}	Bias capacitor	0.1	1		μF
T_J	Operating junction temperature	-40		125	°C

- (1) BIAS supply is required when V_{IN} is below $V_{OUT} + 1.62$ V.

- (2) V_{BIAS} has a minimum voltage of 2.7 V or $V_{OUT} + V_{DO}$ (V_{BIAS}), whichever is higher.

- (3) If V_{IN} and V_{BIAS} are connected to the same supply, the recommended minimum capacitor for the supply is 4.7 μF.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS747 ⁽²⁾		UNIT
		DRC (VSON)	DRC (VSON) ⁽²⁾	
		10 PINS	10 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	41.5	47.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	78	63.7	°C/W
R _{θJB}	Junction-to-board thermal resistance	N/A	19.5	°C/W
ψ _{JT}	Junction-to-top characterization parameter	0.7	4.2	°C/W
ψ _{JB}	Junction-to-board characterization parameter	11.3	19.4	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	6.6	3.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics application report](#).
 (2) M3 suffix.

6.5 Electrical Characteristics: Other Orderable Devices (non-M3 Suffix)

At $V_{EN} = 1.1\text{ V}$, $V_{IN} = V_{OUT} + 0.3\text{ V}$, $C_{BIAS} = 0.1\text{ }\mu\text{F}$, $C_{IN} = C_{OUT} = 10\text{ }\mu\text{F}$, $C_{NR} = 1\text{ nF}$, $I_{OUT} = 50\text{ mA}$, $V_{BIAS} = 5.0\text{ V}$, and $T_J = -40^\circ\text{C}$ to 125°C , (unless otherwise noted); typical values are at $T_J = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{REF}	Internal reference (Adj.)	$T_A = +25^\circ\text{C}$	0.796	0.8	0.804	V
$\Delta V_{OUT} (\Delta V_{IN})$	Output voltage range	$V_{IN} = 5\text{ V}$, $I_{OUT} = 0.5\text{ A}$	V_{REF}		3.6	V
	Accuracy ⁽¹⁾	$2.97\text{ V} \leq V_{BIAS} \leq 5.5\text{ V}$, $50\text{ mA} \leq I_{OUT} \leq 0.5\text{ A}$	-2	± 0.5	2	%
$\Delta V_{OUT} (\Delta I_{OUT})$	Line regulation	$V_{OUT(nom)} + 0.3 \leq V_{IN} \leq 5.5\text{ V}$		0.03		%/V
V_{OUT}	Load regulation	$50\text{ mA} \leq I_{OUT} \leq 0.5\text{ A}$		0.09		%/A
V_{DO}	V_{IN} dropout voltage ⁽²⁾	$I_{OUT} = 0.5\text{ A}$, $V_{BIAS} - V_{OUT(nom)} \geq 3.25\text{ V}^{(3)}$		50	120	mV
	V_{BIAS} dropout voltage ⁽²⁾	$I_{OUT} = 0.5\text{ A}$, $V_{IN} = V_{BIAS}$		1.31	1.39	V
I_{CL}	Output current limit	$V_{OUT} = 80\% \times V_{OUT(nom)}$	800		1350	mA
I_{BIAS}	BIAS pin current			1	2	mA
I_{SHDN}	Shutdown supply current (I_{GND})	$V_{EN} \leq 0.4\text{ V}$		1	50	μA
I_{FB}	Feedback pin current		-1	0.15	1	μA
PSRR	Power-supply rejection (V_{IN} to V_{OUT})	1 kHz, $I_{OUT} = 0.5\text{ A}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		60		dB
		300 kHz, $I_{OUT} = 0.5\text{ A}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		30		dB
	Power-supply rejection (V_{BIAS} to V_{OUT})	1 kHz, $I_{OUT} = 0.5\text{ A}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		50		dB
		300 kHz, $I_{OUT} = 0.5\text{ A}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		30		dB
V_n	Output noise voltage	$\text{BW} = 100\text{ Hz to }100\text{ kHz}$, $I_{OUT} = 0.5\text{ A}$, $C_{SS} = 1\text{ nF}$		25		$\mu\text{Vrms} \times V_{out}$
V_n	Output noise voltage	$\text{BW} = 100\text{ Hz to }100\text{ kHz}$, $I_{OUT} = 0.5\text{ A}$, $C_{SS} = 1\text{ nF}$		$25 \times V_{OUT}$		μVrms
t_{STR}	Minimum start-up time	R_{LOAD} for $I_{OUT} = 0.5\text{ A}$, $C_{SS} = \text{open}$		200		μs
I_{SS}	Soft-start charging current	$V_{SS} = 0.4\text{ V}$		440		nA
$V_{EN(hi)}$	Enable input high level		1.1		5.5	V
$V_{EN(lo)}$	Enable input low level		0		0.4	V
$V_{EN(hys)}$	Enable pin hysteresis			50		mV
$V_{EN(dg)}$	Enable pin deglitch time			20		μs
I_{EN}	Enable pin current	$V_{EN} = 5\text{ V}$		0.1	1	μA
V_{IT}	PG trip threshold	V_{OUT} decreasing	85	90	94	$\%V_{OUT}$
V_{HYS}	PG trip hysteresis			3		$\%V_{OUT}$
$V_{PG(lo)}$	PG output low voltage	$I_{PG} = 1\text{ mA}$ (sinking), $V_{OUT} < V_{IT}$			0.3	V
$I_{PG(lkg)}$	PG leakage current	$V_{PG} = 5.25\text{ V}$, $V_{OUT} > V_{IT}$		0.1	1	μA
T_{SD}	Thermal shutdown temperature	Shutdown, temperature increasing		165		$^\circ\text{C}$
		Reset, temperature decreasing		140		

- (1) Adjustable devices tested at 0.8 V; resistor tolerance is not taken into account.
 (2) Dropout is defined as the voltage from V_{IN} to V_{OUT} when V_{OUT} is 3% below nominal.
 (3) 3.25 V is a test condition of this device and can be adjusted by referring to Figure 6-6.

6.6 Electrical Characteristics: Orderable Device (M3 Suffix)

At $V_{EN} = 1.1\text{ V}$, $V_{IN} = V_{OUT} + 0.3\text{ V}$, $C_{BIAS} = 0.1\text{ }\mu\text{F}$, $C_{IN} = C_{OUT} = 10\text{ }\mu\text{F}$, $C_{NR} = 1\text{ nF}$, $I_{OUT} = 50\text{ mA}$, $V_{BIAS} = 5.0\text{ V}$, and $T_J = -40^\circ\text{C}$ to 125°C , (unless otherwise noted); typical values are at $T_J = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{REF}	Internal reference (Adj.)	$T_A = +25^\circ\text{C}$	0.796	0.8	0.804	V
$\Delta V_{OUT} (\Delta V_{IN})$	Output voltage range	$V_{IN} = 5\text{ V}$, $I_{OUT} = 500\text{ mA}$	V_{REF}		3.6	V
	Accuracy ⁽¹⁾	$2.97\text{ V} \leq V_{BIAS} \leq 5.5\text{ V}$, $50\text{ mA} \leq I_{OUT} \leq 500\text{ mA}$	-0.95	± 0.3	0.95	%
$\Delta V_{OUT} (\Delta I_{OUT})$	Line regulation	$V_{OUT(nom)} + 0.3 \leq V_{IN} \leq 5.5\text{ V}$		0.001		%/V
V_{OUT}	Load regulation	$50\text{ mA} \leq I_{OUT} \leq 500\text{ mA}$		0.11		%/A
V_{DO}	V_{IN} dropout voltage ⁽²⁾	$I_{OUT} = 500\text{ mA}$, $V_{BIAS} - V_{OUT(nom)} \geq 1.62\text{ V}^{(3)}$		20	35	mV
	V_{BIAS} dropout voltage ⁽²⁾	$I_{OUT} = 500\text{ mA}$, $V_{IN} = V_{BIAS}$		1.1	1.25	V
I_{CL}	Output current limit	$V_{OUT} = 80\% \times V_{OUT(nom)}$	800		1300	mA
I_{BIAS}	BIAS pin current			1	1.2	mA
I_{SHDN}	Shutdown supply current (I_{GND})	$V_{EN} \leq 0.4\text{ V}$		0.85	2.75	μA
I_{FB}	Feedback pin current		-30	0.15	30	nA
PSRR	Power-supply rejection (V_{IN} to V_{OUT})	1 kHz, $I_{OUT} = 500\text{ mA}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		76		dB
		300 kHz, $I_{OUT} = 500\text{ mA}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		50		dB
	Power-supply rejection (V_{BIAS} to V_{OUT})	1 kHz, $I_{OUT} = 500\text{ mA}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		59		dB
		300 kHz, $I_{OUT} = 500\text{ mA}$, $V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$		49		dB
V_n	Output noise voltage	$\text{BW} = 100\text{ Hz to } 100\text{ kHz}$, $I_{OUT} = 500\text{ mA}$, $C_{SS} = 1\text{ nF}$		20		$\mu\text{V}_{rms} \times \sqrt{V_{out}}$
t_{STR}	Minimum start-up time	R_{LOAD} for $I_{OUT} = 1.0\text{ A}$, $C_{SS} = \text{open}$		250		μs
I_{SS}	Soft-start charging current	$V_{SS} = 0.4\text{ V}$		530		nA
$V_{EN(hi)}$	Enable input high level		1.1		5.5	V
$V_{EN(lo)}$	Enable input low level		0		0.4	V
$V_{EN(hys)}$	Enable pin hysteresis			55		mV
$V_{EN(dg)}$	Enable pin deglitch time			20		μs
I_{EN}	Enable pin current	$V_{EN} = 5\text{ V}$		0.1	0.25	μA
V_{IT}	PG trip threshold	V_{OUT} decreasing	85	90	94	% V_{OUT}
V_{HYS}	PG trip hysteresis			3		% V_{OUT}
$V_{PG(lo)}$	PG output low voltage	$I_{PG} = 1\text{ mA}$ (sinking), $V_{OUT} < V_{IT}$			0.12	V
$I_{PG(lkg)}$	PG leakage current	$V_{PG} = 5.25\text{ V}$, $V_{OUT} > V_{IT}$		0.001	0.05	μA
T_{SD}	Thermal shutdown temperature	Shutdown, temperature increasing		165		$^\circ\text{C}$
		Reset, temperature decreasing		140		

- (1) Adjustable devices tested at 0.8 V; resistor tolerance is not taken into account.
 (2) Dropout is defined as the voltage from V_{IN} to V_{OUT} when V_{OUT} is 3% below nominal.
 (3) 3.25 V is a test condition of this device and can be adjusted by referring to Figure 6-29.

6.7 Typical Characteristics: $V_{EN} = V_{IN}$ (All Other Orderable Devices, Non-M3 Suffix)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.3\text{ V}$, $V_{BIAS} = 5\text{ V}$, $I_{OUT} = 50\text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{BIAS} = 4.7\text{ }\mu\text{F}$, and $C_{OUT} = 10\text{ }\mu\text{F}$ (unless otherwise noted)

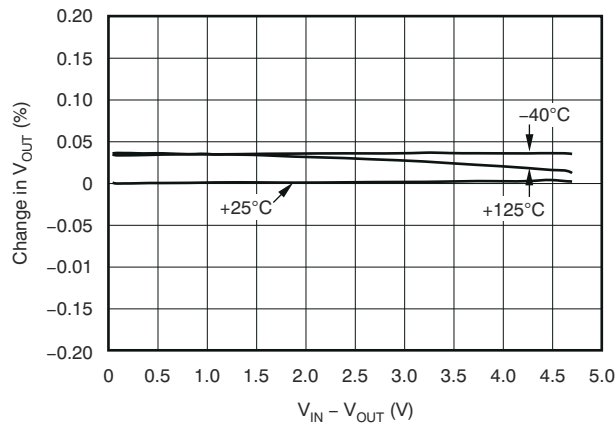


FIG 6-1. V_{IN} Line Regulation

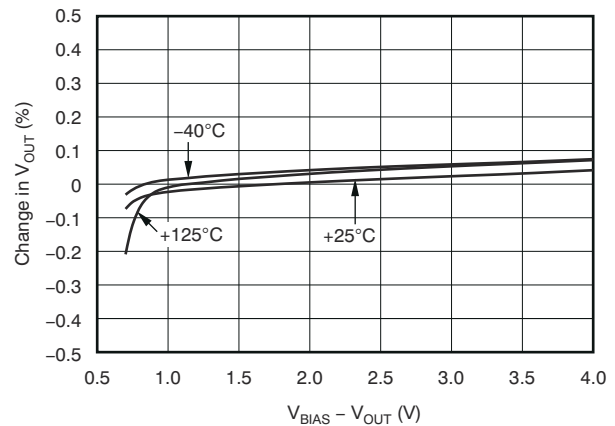


FIG 6-2. V_{BIAS} Line Regulation

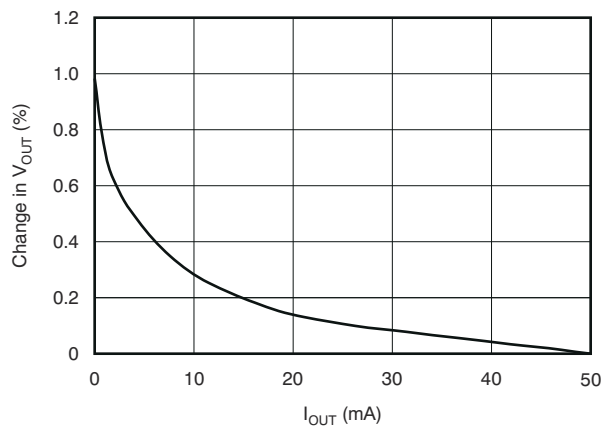


FIG 6-3. Load Regulation

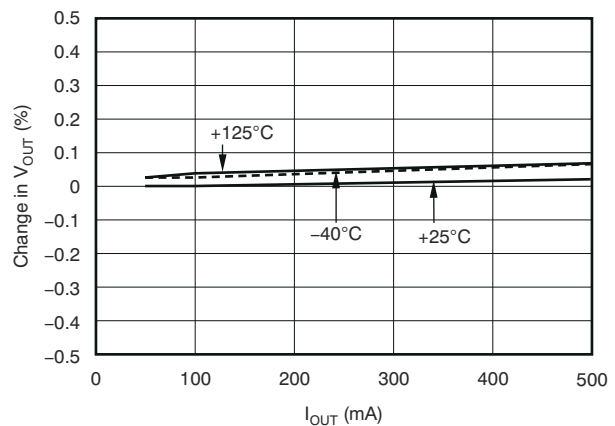


FIG 6-4. Load Regulation

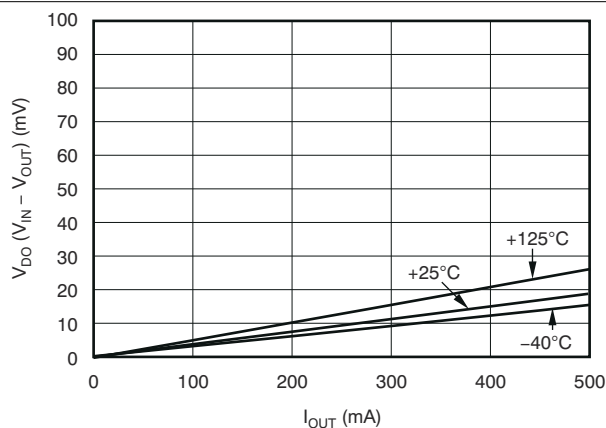


FIG 6-5. Dropout Voltage vs I_{OUT} and Temperature (T_J)

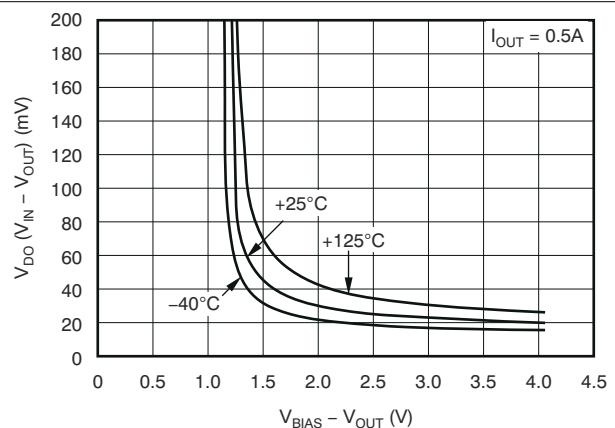


FIG 6-6. Dropout Voltage vs $(V_{BIAS} - V_{OUT})$ and Temperature (T_J)

6.7 Typical Characteristics: $V_{EN} = V_{IN}$ (All Other Orderable Devices, Non-M3 Suffix) (continued)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.3\text{ V}$, $V_{BIAS} = 5\text{ V}$, $I_{OUT} = 50\text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{BIAS} = 4.7\text{ }\mu\text{F}$, and $C_{OUT} = 10\text{ }\mu\text{F}$ (unless otherwise noted)

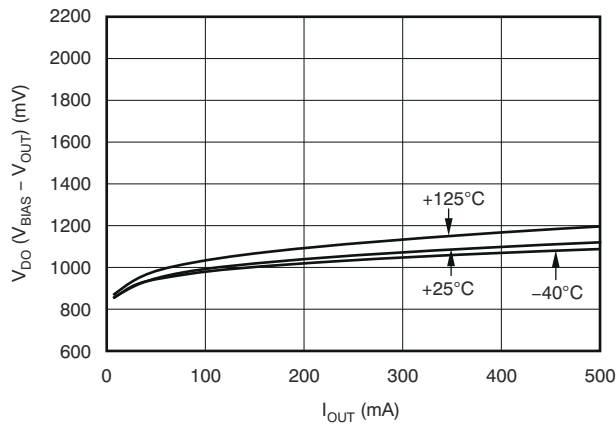


FIG 6-7. V_{BIAS} Dropout Voltage vs I_{OUT} and Temperature (T_J)

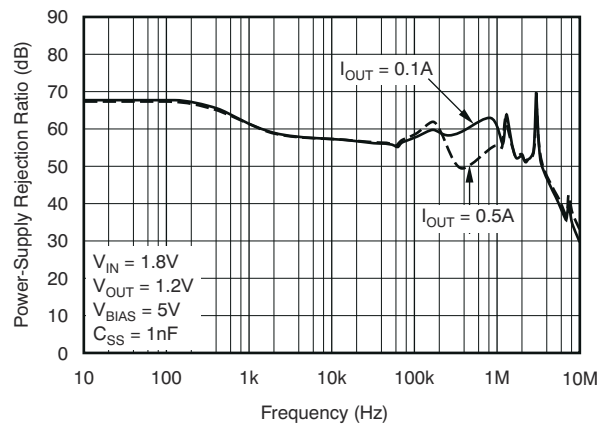


FIG 6-8. V_{BIAS} PSRR vs Frequency

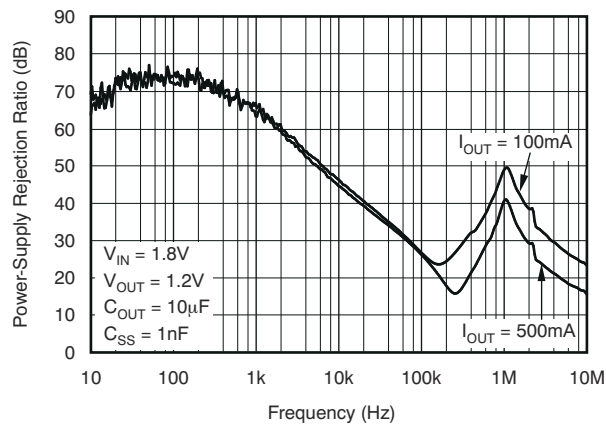


FIG 6-9. V_{IN} PSRR vs Frequency

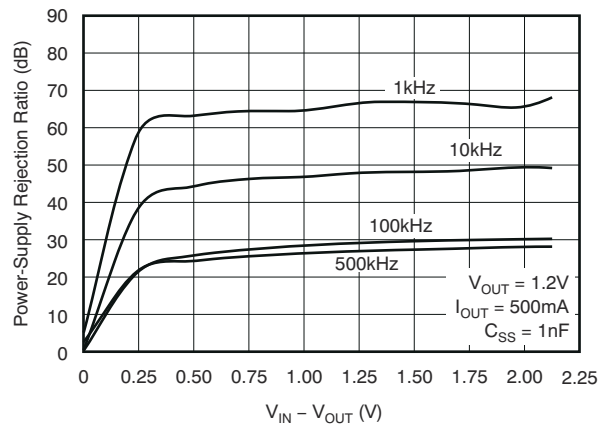


FIG 6-10. V_{IN} PSRR vs ($V_{IN} - V_{OUT}$)

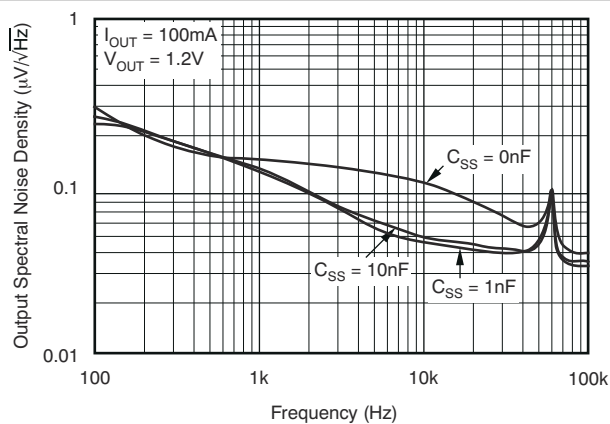


FIG 6-11. Noise Spectral Density

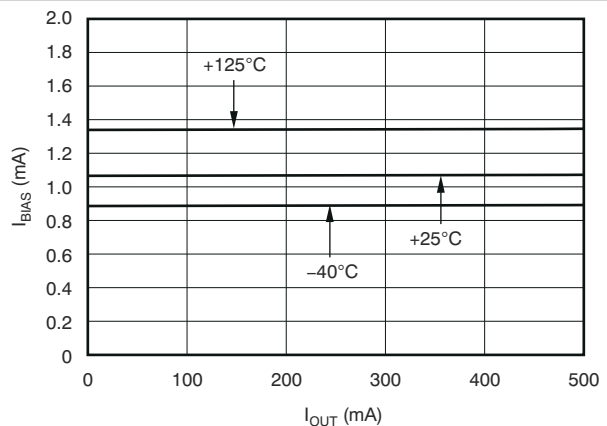


FIG 6-12. BIAS Pin Current vs I_{OUT} and Temperature (T_J)

6.7 Typical Characteristics: $V_{EN} = V_{IN}$ (All Other Orderable Devices, Non-M3 Suffix) (continued)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.3\text{ V}$, $V_{BIAS} = 5\text{ V}$, $I_{OUT} = 50\text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{BIAS} = 4.7\text{ }\mu\text{F}$, and $C_{OUT} = 10\text{ }\mu\text{F}$ (unless otherwise noted)

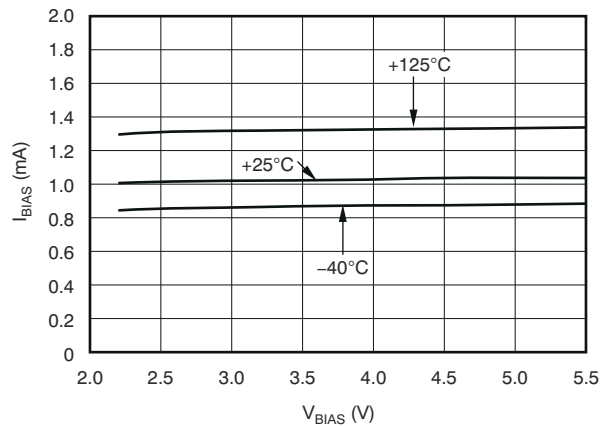


FIG 6-13. BIAS Pin Current vs V_{BIAS} and Temperature (T_J)

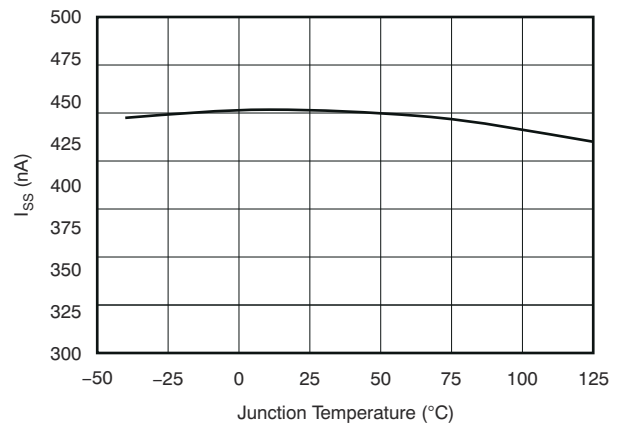


FIG 6-14. Soft-Start Charging Current (I_{SS}) vs Temperature (T_J)

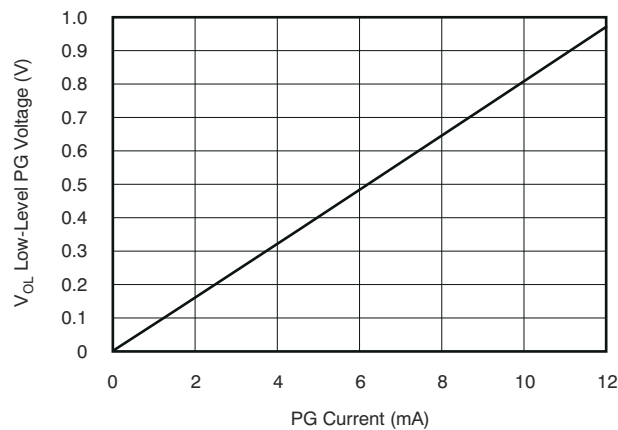


FIG 6-15. Low-Level PG Voltage vs Current

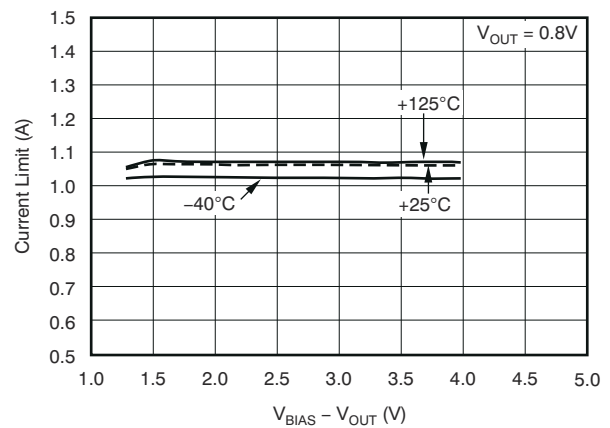


FIG 6-16. Current Limit vs ($V_{BIAS} - V_{OUT}$)

6.8 Typical Characteristics: $V_{EN} = V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$ (All Other Orderable Devices, Non-M3 Suffix)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.3\text{ V}$, $V_{BIAS} = 5\text{ V}$, $I_{OUT} = 50\text{ mA}$, $V_{EN} = V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{BIAS} = 4.7\text{ }\mu\text{F}$, and $C_{OUT} = 10\text{ }\mu\text{F}$ (unless otherwise noted)

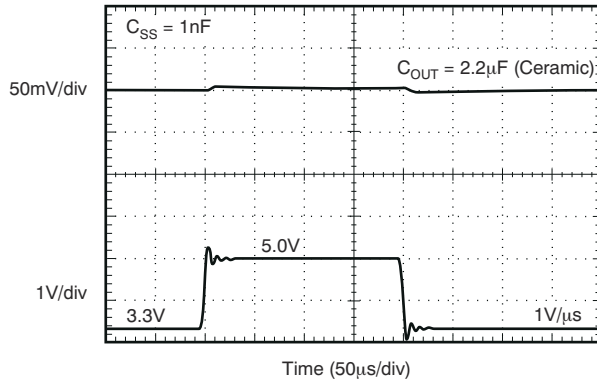


Figure 6-17. V_{BIAS} Line Transient

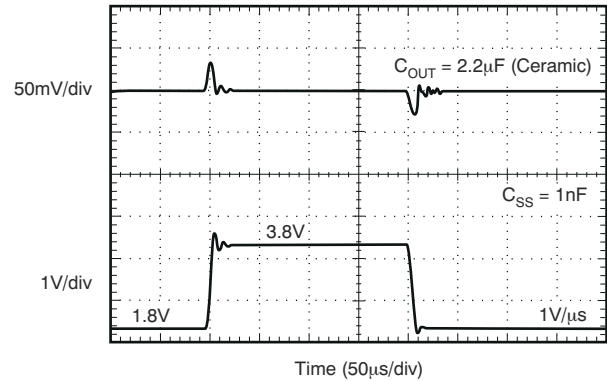


Figure 6-18. V_{IN} Line Transient

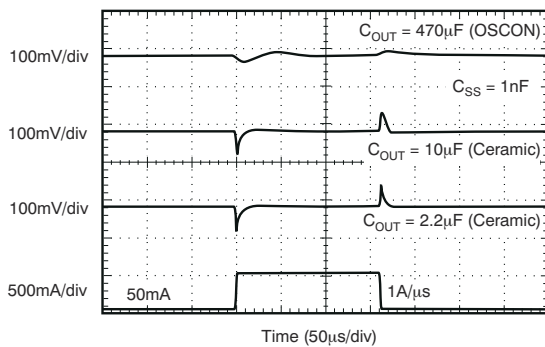


Figure 6-19. Output Load Transient Response

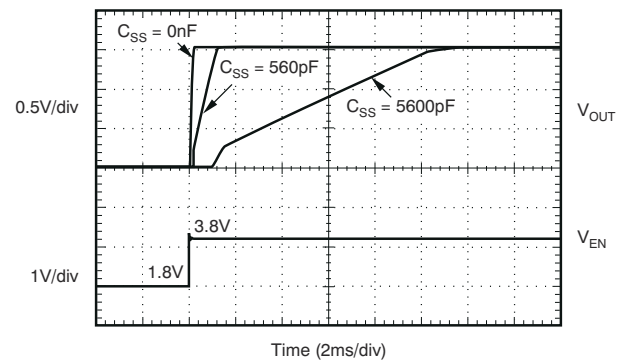


Figure 6-20. Turn-On Response

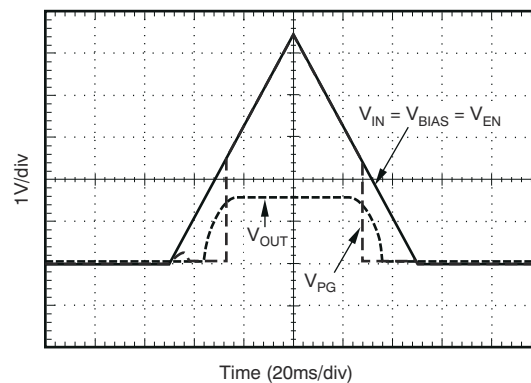
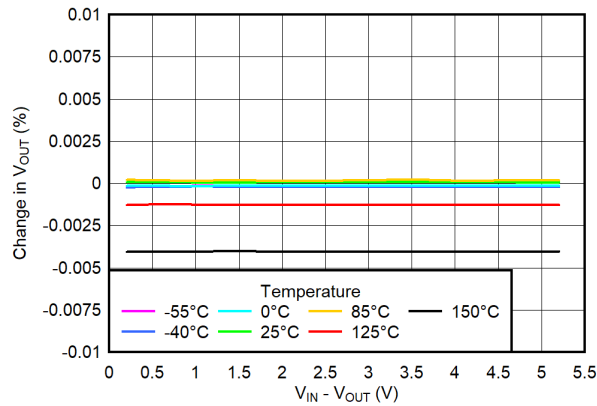


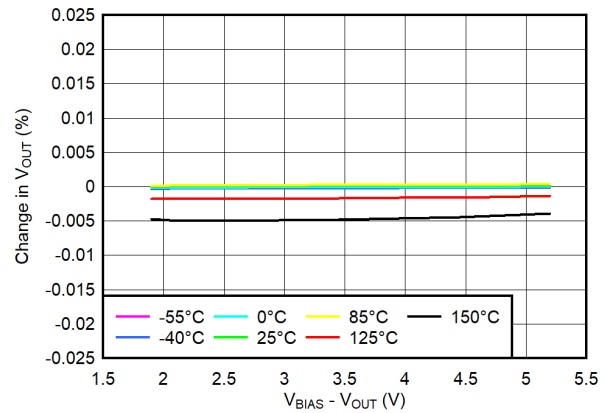
Figure 6-21. Power-Up and Power-Down

6.9 Typical Characteristics: $I_{OUT} = 50 \text{ mA}$ (M3 Suffix)

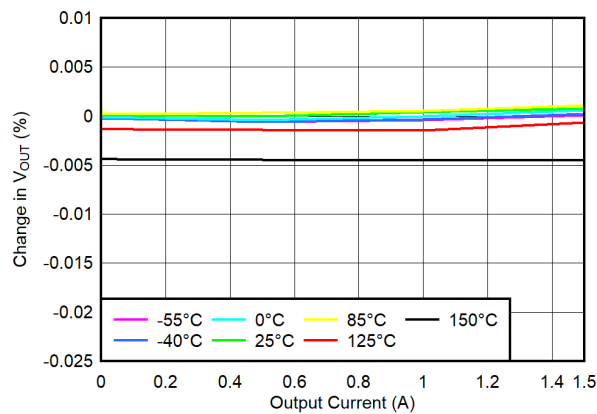
at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(nom)} + 0.3 \text{ V}$, $V_{BIAS} = 5 \text{ V}$, $I_{OUT} = 50 \text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1 \mu\text{F}$, $C_{BIAS} = 4.7 \mu\text{F}$, and $C_{OUT} = 10 \mu\text{F}$ (unless otherwise noted)



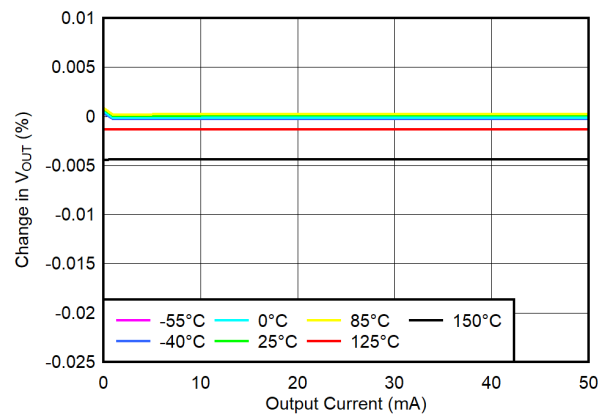
6-22. V_{IN} Line Regulation



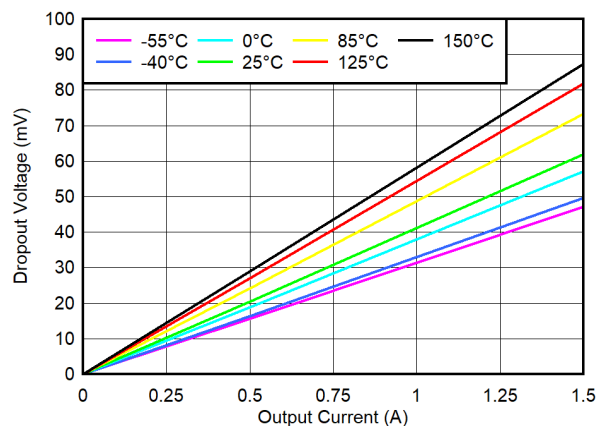
6-23. V_{BIAS} Line Regulation



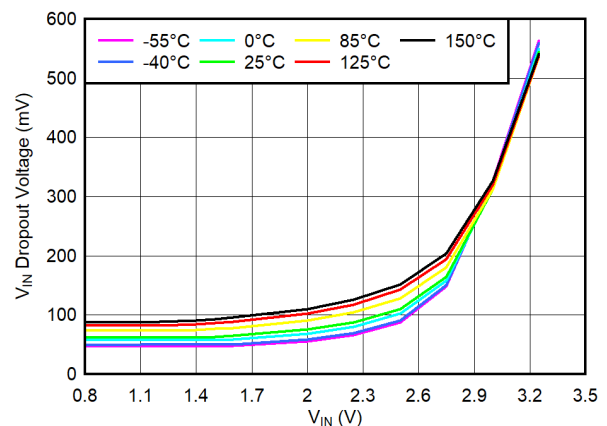
6-24. Load Regulation



6-25. Load Regulation at Light Load



6-26. V_{IN} Dropout Voltage vs I_{OUT} and Temperature (T_J)



6-27. V_{IN} Dropout Voltage vs V_{IN} and Temperature (T_J) for $I_{OUT} = 500 \text{ mA}$

6.9 Typical Characteristics: $I_{OUT} = 50 \text{ mA}$ (M3 Suffix) (continued)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(nom)} + 0.3 \text{ V}$, $V_{BIAS} = 5 \text{ V}$, $I_{OUT} = 50 \text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1 \mu\text{F}$, $C_{BIAS} = 4.7 \mu\text{F}$, and $C_{OUT} = 10 \mu\text{F}$ (unless otherwise noted)

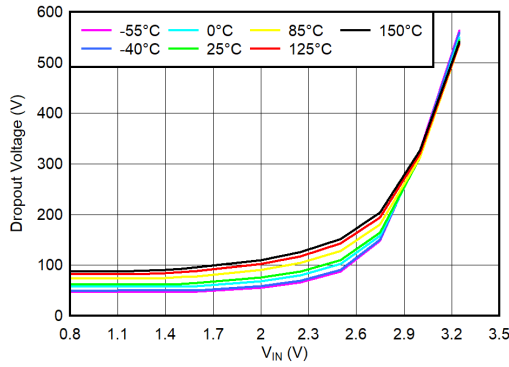


FIG 6-28. V_{IN} Dropout Voltage vs V_{IN} and Temperature (T_J) for $I_{OUT} = 1.5 \text{ A}$

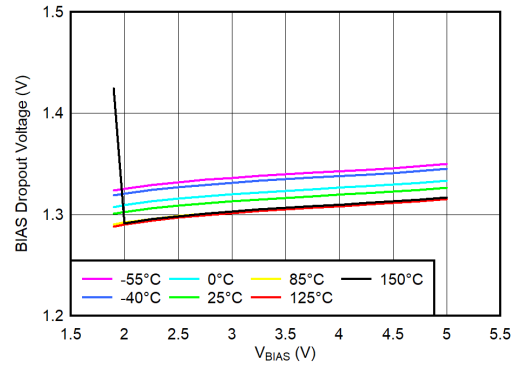


FIG 6-29. V_{IN} Dropout Voltage vs ($V_{BIAS} - V_{OUT}$) and Temperature (T_J)

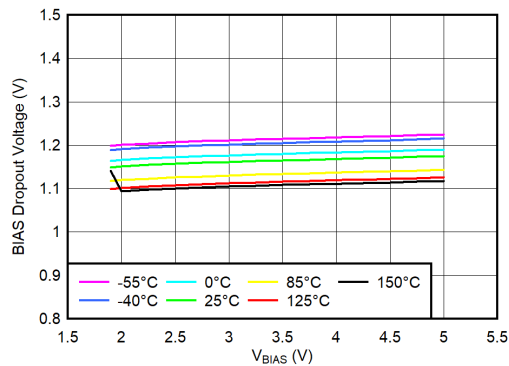


FIG 6-30. V_{IN} Dropout Voltage vs ($V_{BIAS} - V_{OUT}$) and Temperature (T_J)

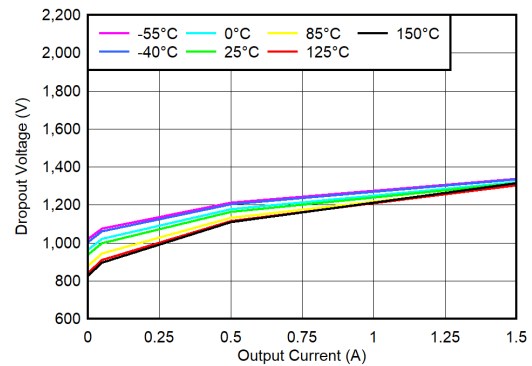


FIG 6-31. V_{BIAS} Dropout Voltage vs I_{OUT} and Temperature (T_J)

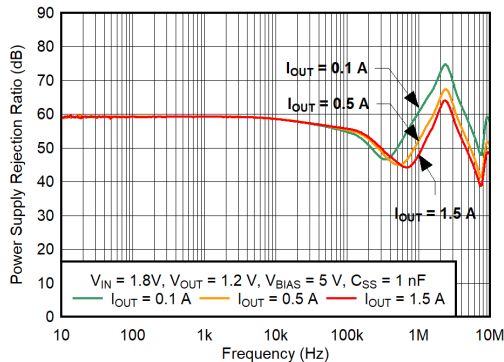


FIG 6-32. V_{BIAS} PSRR vs Frequency

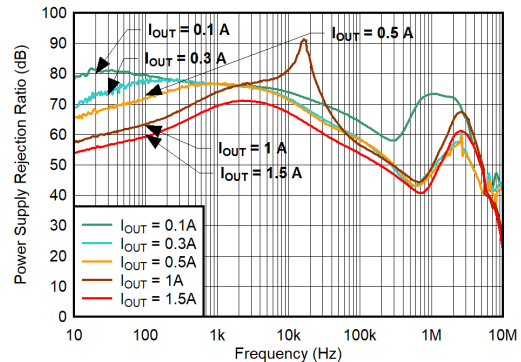


FIG 6-33. V_{IN} PSRR vs Frequency

6.9 Typical Characteristics: $I_{OUT} = 50 \text{ mA}$ (M3 Suffix) (continued)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(nom)} + 0.3 \text{ V}$, $V_{BIAS} = 5 \text{ V}$, $I_{OUT} = 50 \text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1 \mu\text{F}$, $C_{BIAS} = 4.7 \mu\text{F}$, and $C_{OUT} = 10 \mu\text{F}$ (unless otherwise noted)

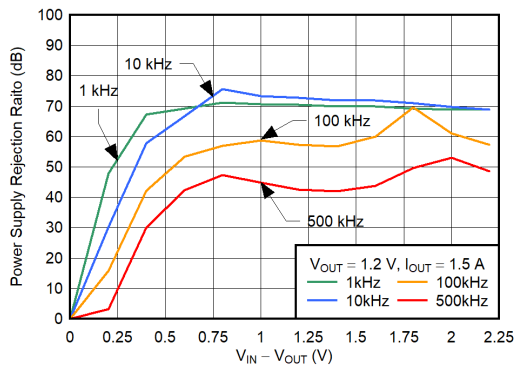


FIG 6-34. V_{IN} PSRR vs $(V_{IN} - V_{OUT})$

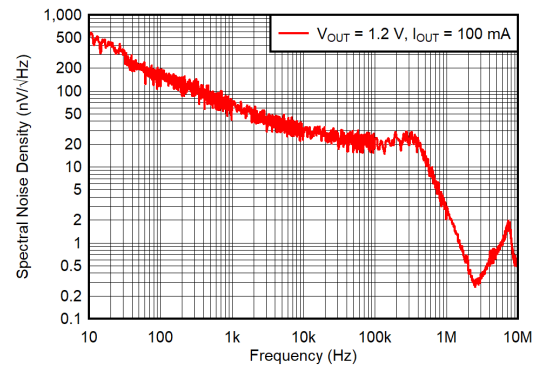


FIG 6-35. Noise Spectral Density

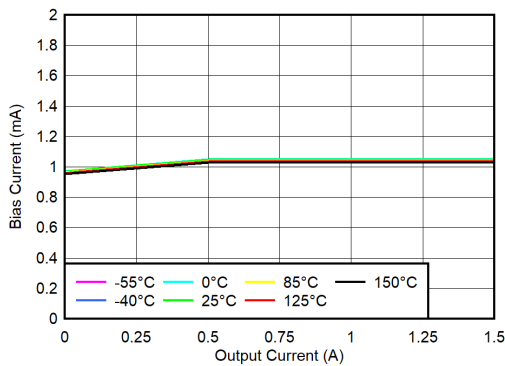


FIG 6-36. BIAS Pin Current vs Output Current and Temperature (T_J)

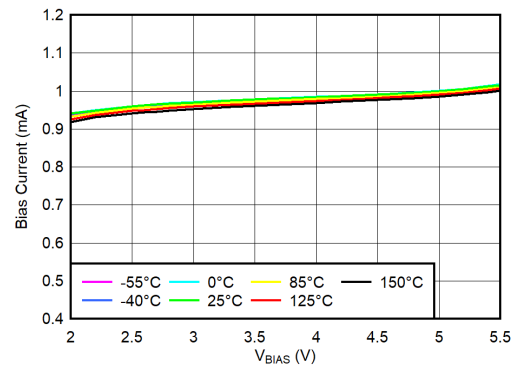


FIG 6-37. BIAS Pin Current vs V_{BIAS} and Temperature (T_J)

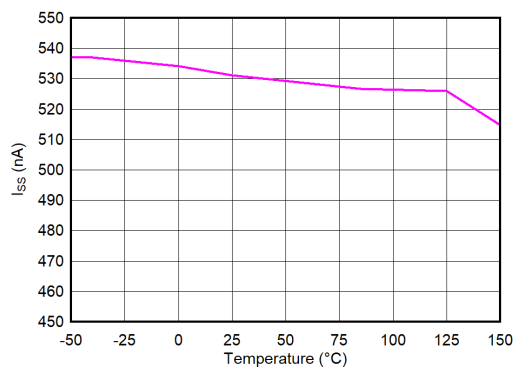


FIG 6-38. Soft-Start Charging Current (I_{SS}) vs Temperature (T_J)

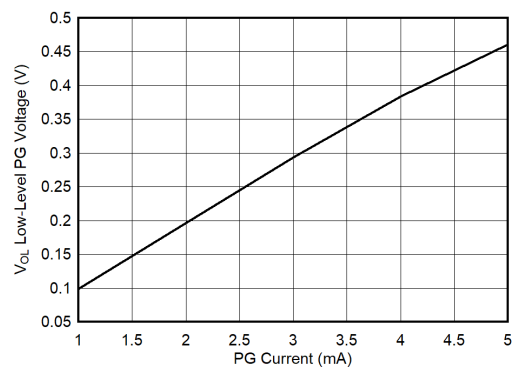


FIG 6-39. Low-Level PG Voltage vs Current

6.9 Typical Characteristics: $I_{OUT} = 50 \text{ mA}$ (M3 Suffix) (continued)

at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(nom)} + 0.3 \text{ V}$, $V_{BIAS} = 5 \text{ V}$, $I_{OUT} = 50 \text{ mA}$, $V_{EN} = V_{IN}$, $C_{IN} = 1 \mu\text{F}$, $C_{BIAS} = 4.7 \mu\text{F}$, and $C_{OUT} = 10 \mu\text{F}$ (unless otherwise noted)

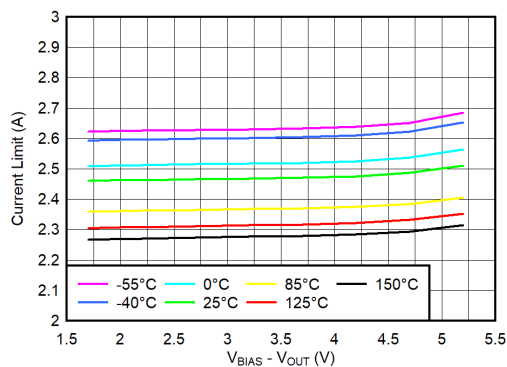
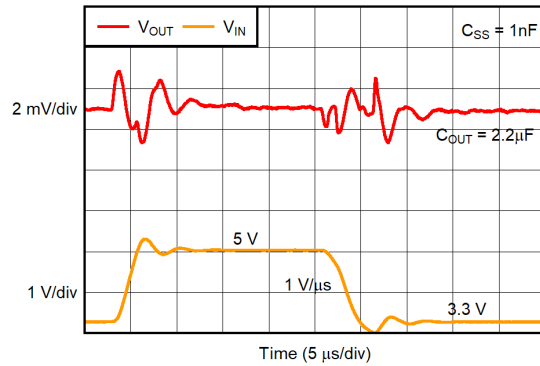


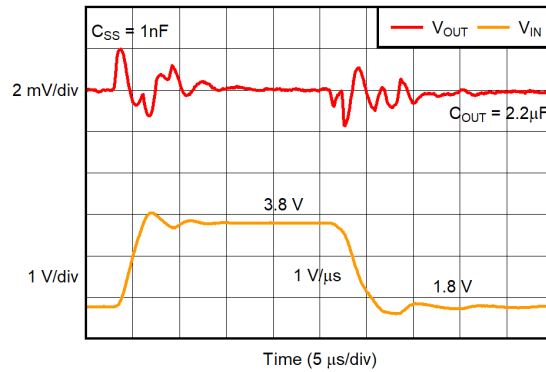
FIG 6-40. Current Limit vs ($V_{BIAS} - V_{OUT}$)

6.10 Typical Characteristics: $V_{EN} = V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$ (M3 Suffix)

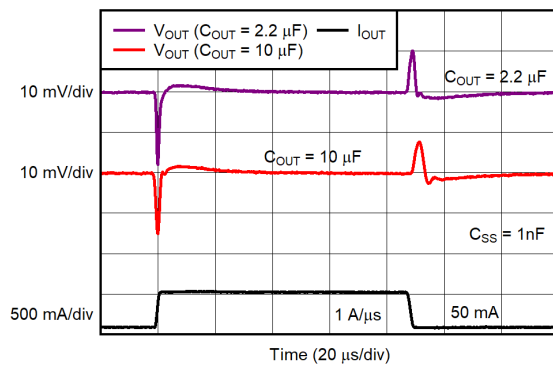
at $T_J = 25^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.3\text{ V}$, $V_{BIAS} = 5\text{ V}$, $I_{OUT} = 50\text{ mA}$, $V_{EN} = V_{IN} = 1.8\text{ V}$, $V_{OUT} = 1.5\text{ V}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{BIAS} = 4.7\text{ }\mu\text{F}$, and $C_{OUT} = 10\text{ }\mu\text{F}$ (unless otherwise noted)



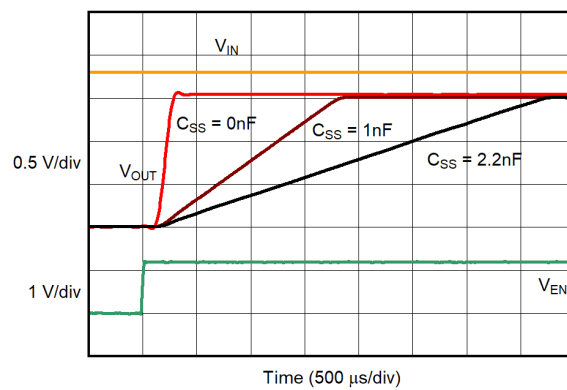
6-41. V_{BIAS} Line Transient



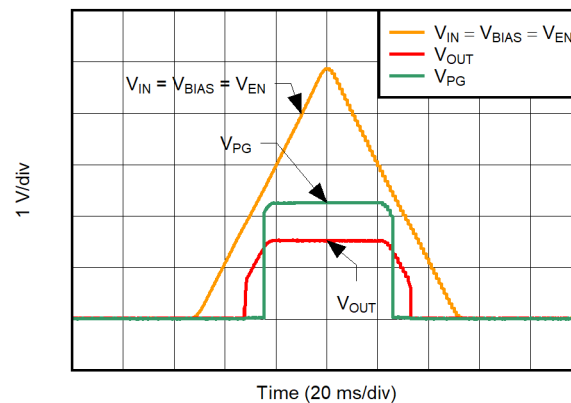
6-42. V_{IN} Line Transient



6-43. Output Load Transient Response



6-44. Turn-On Response



6-45. Power-Up and Power-Down

7 Detailed Description

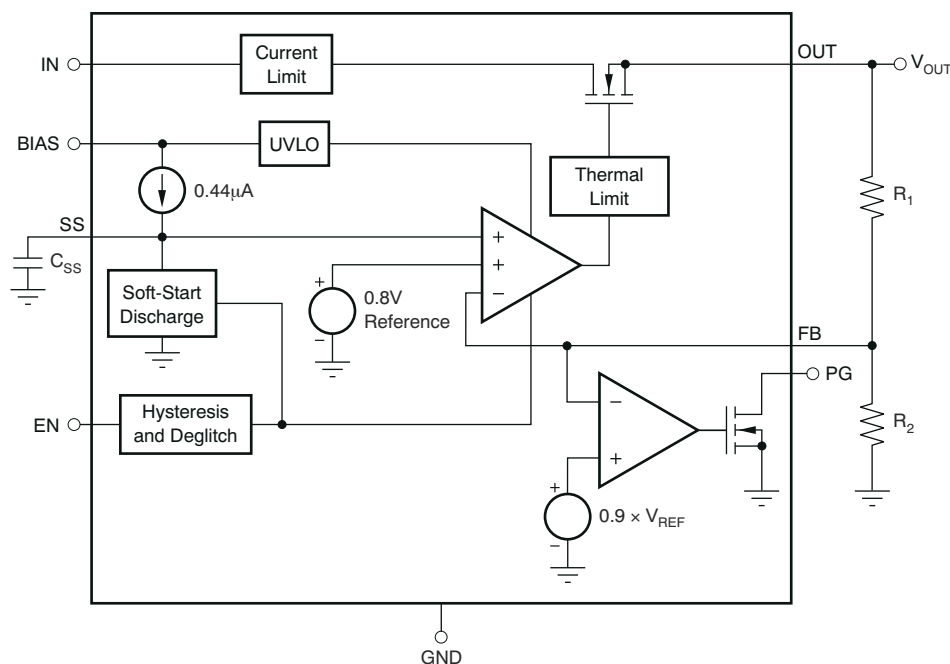
7.1 Overview

The TPS74701 is a low-dropout (LDO) regulator that features soft-start capability. This regulator uses a low current bias input to power all internal control circuitry, allowing the NMOS pass transistor to regulate very low input and output voltages.

The use of an NMOS pass transistor offers several critical advantages for many applications. Unlike a p-channel metal-oxide-semiconductor field effect transistor (PMOS) topology device, the output capacitor has little effect on loop stability. This architecture allows the TPS74701 to be stable with any capacitor type of value 2.2 μF or greater. Transient response is also superior to PMOS topologies, particularly for low V_{IN} applications.

The TPS74701 features a programmable voltage-controlled soft-start circuit that provides a smooth, monotonic start-up and limits start-up inrush currents that can be caused by large capacitive loads. A power-good (PG) output is available to allow supply monitoring and sequencing of other supplies. An enable (EN) pin with hysteresis and deglitch allows slow-ramping signals to be used for sequencing the device. The low V_{IN} and V_{OUT} capability allows for inexpensive, easy-to-design, and efficient linear regulation between the multiple supply voltages often present in processor-intensive systems.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Programmable Soft-Start

The TPS74701 features a programmable, monotonic, voltage-controlled soft-start that is set with an external capacitor (C_{SS}). This feature is important for many applications because soft-start eliminates power-up initialization problems when powering FPGAs, DSPs, or other processors. The controlled voltage ramp of the output also reduces peak inrush current during start-up, minimizing start-up transient events to the input power bus.

To achieve a linear and monotonic soft-start, the TPS74701 error amplifier tracks the voltage ramp of the external soft-start capacitor until the voltage exceeds the internal reference. The soft-start ramp time depends on the soft-start charging current (I_{SS}), soft-start capacitance (C_{SS}), and the internal reference voltage (V_{REF}), and can be calculated using 式 1:

$$t_{SS} = \frac{(V_{REF} \times C_{SS})}{I_{SS}} \quad (1)$$

If large output capacitors are used, the device current limit (I_{CL}) and the output capacitor can set the start-up time. In this case, the start-up time is given by 式 2:

$$t_{SSCL} = \frac{(V_{OUT(NOM)} \times C_{OUT})}{I_{CL(MIN)}} \quad (2)$$

where:

- $V_{OUT(NOM)}$ is the nominal output voltage
- C_{OUT} is the output capacitance
- $I_{CL(MIN)}$ is the minimum current limit for the device

In applications where monotonic start-up is required, the soft-start time given by 式 1 must be set greater than 式 2.

The maximum recommended soft-start capacitor is 0.015 μ F. Larger soft-start capacitors can be used, and do not damage the device; however, the soft-start capacitor discharge circuit can possibly be unable to fully discharge the soft-start capacitor when enabled.

Soft-start capacitors larger than 0.015 μ F can be a problem in applications where the enable pin must be rapidly pulsed while still requiring the device to soft-start from ground. C_{SS} must be low-leakage; X7R, X5R, or C0G dielectric materials are preferred. See 表 8-2 for suggested soft-start capacitor values.

7.3.2 Enable and Shutdown

The enable (EN) pin is active high and is compatible with standard digital signaling levels. V_{EN} below 0.4 V turns the regulator off, while V_{EN} above 1.1 V turns the regulator on. Unlike many regulators, the enable circuitry has hysteresis and deglitching for use with relatively slowly ramping analog signals. This configuration allows the TPS74701 to be enabled by connecting the output of another supply to the EN pin. The enable circuitry typically has 50 mV of hysteresis and a deglitch circuit to help avoid on-off cycling as a result of small glitches in the V_{EN} signal.

The enable threshold is typically 0.8 V and varies with temperature and process variations. Temperature variation is approximately -1 mV/ $^{\circ}$ C; process variation accounts for most of the rest of the variation to the 0.4-V and 1.1-V limits. If precise turn-on timing is required, a fast rise-time signal must be used to enable the TPS74701.

If not used, EN can be connected to either IN or BIAS. If EN is connected to IN, connect this pin as close as possible to the largest capacitance on the input to prevent voltage droops on that line from triggering the enable circuit.

7.3.3 Power Good

The power-good (PG) pin is an open-drain output and can be connected to any 5.5-V or lower rail through an external pullup resistor. This pin requires at least 1.1 V on V_{BIAS} to have a valid output. The PG output is high-impedance when V_{OUT} is greater than $V_{IT} + V_{HYS}$. If V_{OUT} drops below V_{IT} or if V_{BIAS} drops below 1.9 V, the open-drain output turns on and pulls the PG output low. The PG pin also asserts when the device is disabled. The recommended operating condition of the PG pin sink current is up to 1 mA, so the pullup resistor for PG must be in the range of 10 k Ω to 1 M Ω . If output voltage monitoring is not needed, the PG pin can be left floating.

7.3.4 Internal Current Limit

The TPS74701 features a factory-trimmed, accurate current limit that is flat over temperature and supply voltage. The current limit allows the device to supply surges of up to 1 A and maintain regulation. The current limit responds in approximately 10 μ s to reduce the current during a short-circuit fault.

The internal current limit protection circuitry of the TPS74701 is designed to protect against overload conditions. This circuitry is not intended to allow operation above the rated current of the device. Continuously running the TPS74701 above the rated current degrades device reliability.

7.3.5 Thermal Shutdown

Thermal protection disables the output when the junction temperature rises to approximately 160°C, allowing the device to cool. When the junction temperature cools to approximately 140°C, the output circuitry is enabled. Depending on power dissipation, thermal resistance, and ambient temperature the thermal protection circuit can cycle on and off. This cycling limits the dissipation of the regulator, protecting the regulator from damage as a result of overheating.

Activation of the thermal protection circuit indicates excessive power dissipation or inadequate heat sinking. For reliable operation, junction temperature must be limited to 125°C maximum. To estimate the margin of safety in a complete design (including heat sink), increase the ambient temperature until thermal protection is triggered; use worst-case loads and signal conditions. For good reliability, thermal protection must trigger at least 40°C above the maximum expected ambient condition of the application. This condition produces a worst-case junction temperature of 125°C at the highest expected ambient temperature and worst-case load.

The internal protection circuitry of the TPS74701 is designed to protect against overload conditions. This circuitry is not intended to replace proper heat sinking. Continuously running the TPS74701 into thermal shutdown degrades device reliability.

7.4 Device Functional Modes

表 7-1 shows the conditions that lead to the different modes of operation.

表 7-1. Device Functional Mode Comparison

OPERATING MODE	PARAMETER				
	V_{IN}	V_{EN}	V_{BIAS}	I_{OUT}	T_J
Normal mode	$V_{IN} > V_{OUT(nom)} + V_{DO}(V_{IN})$	$V_{EN} > V_{EN, HI}$	$V_{BIAS} \geq V_{OUT} + 1.39\text{ V}$	$I_{OUT} < I_{CL}$	$T_J < 125^\circ\text{C}$
Dropout mode	$V_{IN} < V_{OUT(nom)} + V_{DO}(V_{IN})$	$V_{EN} > V_{EN, HI}$	$V_{BIAS} < V_{OUT} + 1.39\text{ V}$	—	$T_J < 125^\circ\text{C}$
Disabled mode (any true condition disables the device)	$V_{IN} < V_{IN(min)}$	$V_{EN} < V_{EN, LO}$	$V_{BIAS} < V_{BIAS(min)}$	—	$T_J > 165^\circ\text{C}$

7.4.1 Normal Operation

The device regulates to the nominal output voltage under the following conditions:

- The input voltage and bias voltage are both at least at the respective minimum specifications
- The enable voltage has previously exceeded the enable rising threshold voltage and has not decreased below the enable falling threshold
- The output current is less than the current limit
- The device junction temperature is less than the maximum specified junction temperature

7.4.2 Dropout Operation

If the input voltage is lower than the nominal output voltage plus the specified dropout voltage, but all other conditions are met for normal operation, the device operates in dropout mode. In this condition, the output voltage is the same as the input voltage minus the dropout voltage. The transient performance of the device is significantly degraded because the pass transistor is in a triode state and no longer controls the current through the LDO. Line or load transients in dropout can result in large output voltage deviations.

7.4.3 Disabled

The device is disabled under the following conditions:

- The input or bias voltages are below the respective minimum specifications
- The enable voltage is less than the enable falling threshold voltage or has not yet exceeded the enable rising threshold
- The device junction temperature is greater than the thermal shutdown temperature

8 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

R_1 and R_2 can be calculated for any output voltage using the formula in 図 8-4. 表 8-1 lists sample resistor values of common output voltages. To achieve the maximum accuracy specifications, R_2 must be less than or equal to 4.99 k Ω . 表 8-2 lists the capacitor values for setting the soft-start time.

表 8-1. Standard 1% Resistor Values for Programming the Output Voltage⁽¹⁾

R_1 (k Ω)	R_2 (k Ω)	V_{OUT} (V)
Short	Open	0.8
0.619	4.99	0.9
1.13	4.53	1
1.37	4.42	1.05
1.87	4.99	1.1
2.49	4.99	1.2
4.12	4.75	1.5
3.57	2.87	1.8
3.57	1.69	2.5
3.57	1.15	3.3

(1) $V_{OUT} = 0.8 \times (1 + R_1 / R_2)$.

表 8-2. Standard Capacitor Values for Programming the Soft-Start Time⁽¹⁾

C_{SS}	SOFT-START TIME
Open	0.1 ms
270 pF	0.5 ms
560 pF	1 ms
2.7 nF	5 ms
5.6 nF	10 ms
0.01 μ F	18 ms

(1)
$$t_{SS}(s) = \frac{V_{REF} \times C_{SS}}{I_{SS}} = \frac{0.8V \times C_{SS}(F)}{0.44\mu A}$$
 where $t_{SS}(s)$ = soft-start time in seconds.

8.1.1 Input, Output, and Bias Capacitor Requirements

The device is designed to be stable for all available types and values of output capacitors greater than or equal to 2.2 μ F. The device is also stable with multiple capacitors in parallel, which can be of any type or value.

The capacitance required on the IN and BIAS pins strongly depends on the input supply source impedance. To counteract any inductance in the input, the minimum recommended capacitor for V_{IN} and V_{BIAS} is 1 μ F. If V_{IN} and V_{BIAS} are connected to the same supply, the recommended minimum capacitor for V_{BIAS} is 4.7 μ F. Use good-quality, low-ESR capacitors on the input; ceramic X5R and X7R capacitors are preferred. Place these capacitors as close the pins as possible for optimum performance.

8.1.2 Transient Response

The TPS74701 was designed to have excellent transient response for most applications with a small amount of output capacitance. In some cases, the transient response can be limited by the transient response of the input supply. This limitation is especially true in applications where the difference between the input and output is less than 300 mV. In this case, adding additional input capacitance improves the transient response much more than just adding additional output capacitance otherwise does. With a solid input supply, adding additional output capacitance reduces undershoot and overshoot during a transient event; see [Figure 6-43](#) in the [Typical Characteristics](#) section. Because the TPS74701 is stable with output capacitors as low as 2.2 μF , many applications can then need very little capacitance at the LDO output. For these applications, local bypass capacitance for the powered device can be sufficient to meet the transient requirements of the application. This design reduces the total solution cost by avoiding the need to use expensive, high-value capacitors at the LDO output.

8.1.3 Dropout Voltage

The TPS74701 offers very low dropout performance, making the device designed for high-current, low V_{IN} and low V_{OUT} applications. The low dropout of the TPS74701 allows the device to be used in place of a DC/DC converter and still achieve good efficiency. This feature provides designers with the power architecture for applications to achieve the smallest, simplest, and lowest cost solution.

There are two different specifications for dropout voltage with the TPS74701. The first specification (shown in [Figure 8-1](#)) is referred to as V_{IN} dropout and is used when an external bias voltage is applied to achieve low dropout. This specification assumes that V_{BIAS} is at least 1.39 V¹ above V_{OUT} , which is the case for V_{BIAS} when powered by a 3.3-V rail with 5% tolerance and with $V_{\text{OUT}} = 1.5\text{ V}$. If V_{BIAS} is higher than $V_{\text{OUT}} + 1.39\text{ V}$ ¹, V_{IN} dropout is less than specified.¹

The second specification (shown in [Figure 8-2](#)) is referred to as V_{BIAS} dropout and applies to applications where IN and BIAS are tied together. This option allows the device to be used in applications where an auxiliary bias voltage is not available or low dropout is not required. Dropout is limited by BIAS in these applications because V_{BIAS} provides the gate drive to the pass transistor; therefore, V_{BIAS} must be 1.39 V above V_{OUT} . Because of this usage, IN and BIAS tied together easily consume a huge amount of power. Pay attention not to exceed the power rating of the device package.

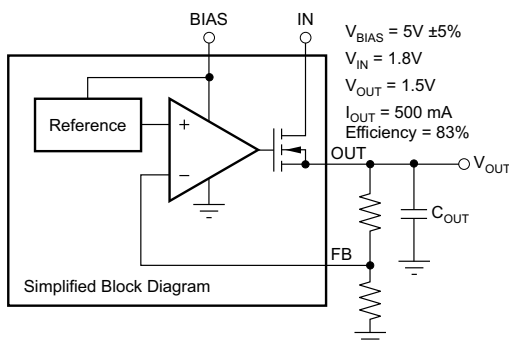


Figure 8-1. Typical Application of the TPS74701 Using an Auxiliary Bias Rail

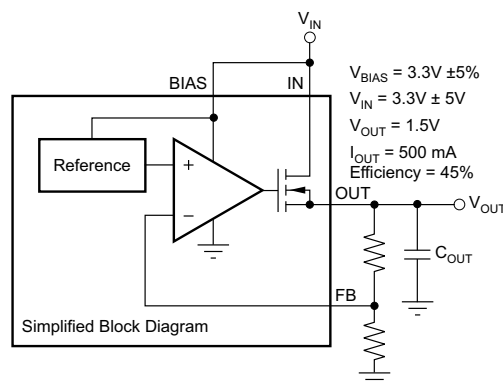


Figure 8-2. Typical Application of the TPS74701 Without an Auxiliary Bias Rail

¹ 1.62 V is a test condition of this device and can be adjusted by referring to [Figure 6-6](#).

8.1.4 Sequencing Requirements

V_{IN} , V_{BIAS} , and V_{EN} can be sequenced in any order without causing damage to the device. However, for the soft-start function to work as intended, certain sequencing rules must be applied. Connecting EN to IN is acceptable for most applications, as long as V_{IN} is greater than 1.1 V and the ramp rate of V_{IN} and V_{BIAS} is faster than the set soft-start ramp rate. If the ramp rate of the input sources is slower than the set soft-start time, the output tracks the slower supply minus the dropout voltage until the set output voltage is reached. If EN is connected to BIAS, the device soft-starts as programmed, provided that V_{IN} is present before V_{BIAS} . If V_{BIAS} and V_{EN} are present before V_{IN} is applied and the set soft-start time has expired, then V_{OUT} tracks V_{IN} . If the soft-start time has not expired, the output tracks V_{IN} until V_{OUT} reaches the value set by the charging soft-start capacitor. [Figure 8-3](#) shows the use of an RC-delay circuit to hold off V_{EN} until V_{BIAS} has ramped. This technique can also be used to drive EN from V_{IN} . An external control signal can also be used to enable the device after V_{IN} and V_{BIAS} are present.

注

When V_{BIAS} and V_{EN} are present and V_{IN} is not supplied, this device outputs approximately 50 μ A of current from OUT. Although this condition does not cause any damage to the device, the output current can charge up the OUT node if total resistance between OUT and GND (including external feedback resistors) is greater than 10 k Ω .

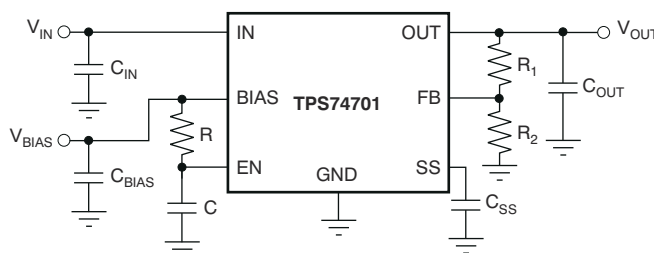


Figure 8-3. Soft-Start Delay Using an RC Circuit to Enable the Device

8.1.5 Output Noise

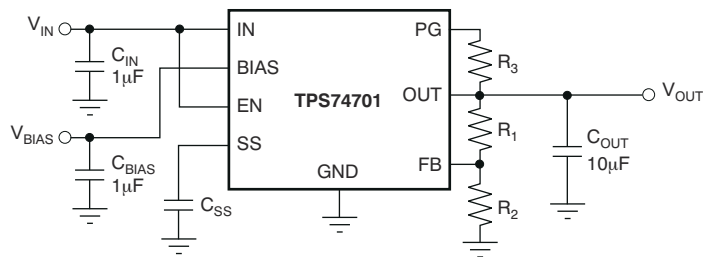
The TPS74701 provides low-output noise when a soft-start capacitor is used. When the device reaches the end of the soft-start cycle, the soft-start capacitor serves as a filter for the internal reference. By using a 0.001- μ F soft-start capacitor, the output noise is reduced by half and is typically 30 μ V_{RMS} for a 1.2-V output (10 Hz to 100 kHz). Further increasing C_{SS} has little effect on noise. Because most of the output noise is generated by the internal reference, the noise is a function of the set output voltage. The RMS noise with a 0.001- μ F soft-start capacitor is given in [Equation 3](#):

$$V_N(\mu\text{V}_{\text{RMS}}) = 25 \left(\frac{\mu\text{V}_{\text{RMS}}}{\text{V}} \right) \times V_{\text{OUT}}(\text{V}) \quad (3)$$

The low-output noise of the TPS74701 makes the device a good choice for powering transceivers, PLLs, or other noise-sensitive circuitry.

8.2 Typical Application

Figure 8-4 shows a typical application circuit for the TPS74701 adjustable output device.



$$V_{OUT} = 0.8 \times \left(1 + \frac{R_1}{R_2} \right)$$

Figure 8-4. Typical Application Circuit for the TPS74701 (Adjustable)

8.2.1 Design Requirements

Table 8-3 shows the design parameters for this application.

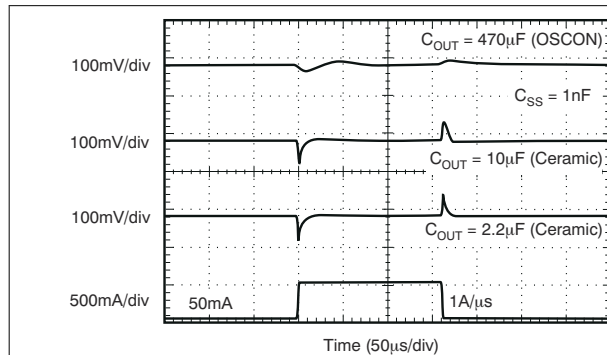
Table 8-3. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
V_{IN}	1.8 V $\pm$ 10%
V_{BIAS}	3.3 V $\pm$ 10%
V_{OUT}	1.5 V $\pm$ 3%
I_{OUT}	500 mA
Start-up time	< 2 ms

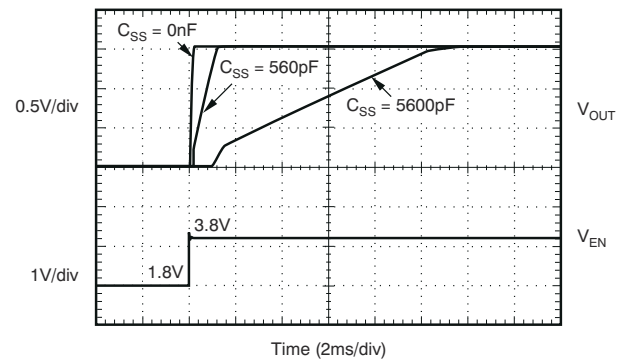
8.2.2 Detailed Design Procedure

1. Select R_1 and R_2 based on the required output voltage. Table 8-1 gives example calculations for many common output voltages.
2. Select C_{SS} to be the highest capacitance while still achieving the desired start-up time. Table 8-2 gives examples of this calculation.
3. Select a minimum of a 2.2-µF ceramic output capacitor. Increased output capacitance helps the output load transient response. Figure 8-6 gives examples of the load transient response with different output capacitor values and types.

8.2.3 Application Curves



8-5. Output Load Transient Response



8-6. Turn-On Response

8.3 Power Supply Recommendations

The TPS74701 is designed to operate from an input voltage up to 5.5 V, provided the bias rail is at least 1.39-V higher than the input supply and dropout requirements are met. The bias rail and the input supply must both provide adequate headroom and current for the device to operate normally. Connect a low-output impedance power supply directly to the IN pin of the TPS74701. This supply must have at least 1 µF of capacitance near the IN pin for optimal performance. A supply with similar requirements must also be connected directly to the bias rail with a separate 1-µF or larger capacitor. If the IN pin is tied to the bias pin, a minimum 4.7 µF of capacitance is needed for performance. To increase the overall PSRR of the solution at higher frequencies, use a pi-filter or ferrite bead before the input capacitor.

8.4 Layout

8.4.1 Layout Guidelines

An optimal layout can greatly improve transient performance, PSRR, and noise. To minimize the voltage droop on the input of the device during load transients, connect the capacitance on IN, OUT, and BIAS as close as possible to the device. If BIAS is connected to IN, connect BIAS as close to the input supply as possible. This connection minimizes the voltage droop on BIAS during transient conditions and can improve the turn-on response.

8.4.1.1 Power Dissipation

An optimal layout can greatly improve transient performance, PSRR, and noise. To minimize the voltage drop on the input of the device during load transients, the capacitance on IN and BIAS must be connected as close as possible to the device. This capacitance also minimizes the effects of parasitic inductance and resistance of the input source and can therefore improve stability. To achieve optimal transient performance and accuracy, the top side of R₁ in 8-4 must be connected as close as possible to the load. If BIAS is connected to IN, connect BIAS as close to the sense point of the input supply as possible. This connection minimizes the voltage drop on BIAS during transient conditions and can improve the turn-on response.

Knowing the device power dissipation and proper sizing of the thermal plane that is connected to the thermal pad is critical to avoiding thermal shutdown and ensuring reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated using 式 4:

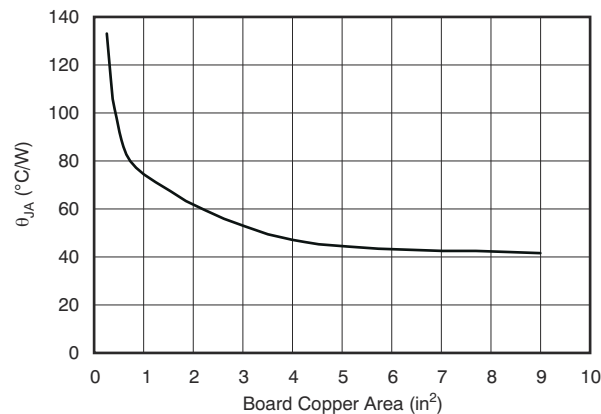
$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (4)$$

Power dissipation can be minimized and greater efficiency can be achieved by using the lowest possible input voltage necessary to achieve the required output voltage regulation.

On the VSON (DRC) package, the primary conduction path for heat is through the exposed pad to the printed-circuit-board (PCB). The pad can be connected to ground or be left floating; however, the pad must be attached to an appropriate amount of copper PCB area to make sure the device does not overheat. The maximum junction-to-ambient thermal resistance depends on the maximum ambient temperature, maximum device junction temperature, and power dissipation of the device and can be calculated using 式 5:

$$R_{\theta JA} = \frac{(+125^{\circ}\text{C} - T_A)}{P_D} \quad (5)$$

Knowing the maximum $R_{\theta JA}$, the minimum amount of PCB copper area needed for appropriate heat sinking can be estimated using 図 8-7.



$R_{\theta JA}$ value at board size of 9 in² (that is, 3 inches × 3 inches) is a JEDEC standard.

図 8-7. $R_{\theta JA}$ vs Board Size

図 8-7 shows the variation of $R_{\theta JA}$ as a function of ground plane copper area in the board. This figure is intended only as a guideline to demonstrate the effects of heat spreading in the ground plane and is not meant to be used to estimate actual thermal performance in real application environments.

注

When the device is mounted on an application PCB, TI strongly recommends using Ψ_{JT} and Ψ_{JB} , as explained in the [Estimating Junction Temperature](#) section.

8.4.1.2 Estimating Junction Temperature

Using the thermal metrics Ψ_{JT} and Ψ_{JB} , as shown in the [Thermal Information](#) table, the junction temperature can be estimated with corresponding formulas (given in 式 6). For backwards compatibility, an older $R_{\theta JC}$, *Top* parameter is listed as well.

$$\begin{aligned} \Psi_{JT}: \quad T_J &= T_T + \Psi_{JT} \cdot P_D \\ \Psi_{JB}: \quad T_J &= T_B + \Psi_{JB} \cdot P_D \end{aligned} \quad (6)$$

where:

- P_D is the power dissipation shown by 式 5
- T_T is the temperature at the center-top of the device package
- T_B is the PCB temperature measured 1mm away from the device package *on the PCB surface* (as 図 8-9 shows)

注

Both T_T and T_B can be measured on actual application boards using a thermo-gun (an infrared thermometer).

For more information about measuring T_T and T_B , see the [Using New Thermal Metrics application note](#), available for download at www.ti.com.

From 図 8-8, the new thermal metrics (Ψ_{JT} and Ψ_{JB}) obviously have very little dependency on board size. That is, using Ψ_{JT} or Ψ_{JB} with 式 6 is a good way to estimate T_J by simply measuring T_T or T_B , regardless of the application board size.

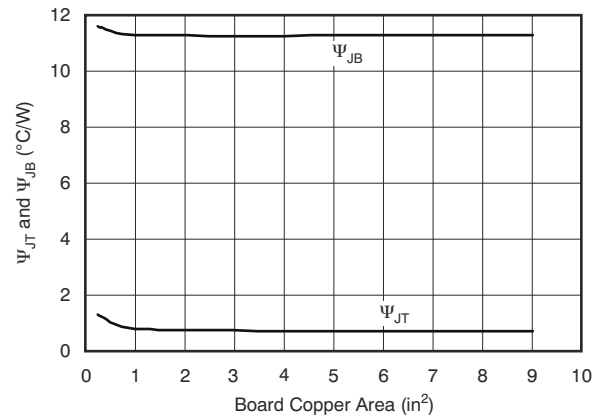


図 8-8. Ψ_{JT} and Ψ_{JB} vs Board Size

For a more detailed discussion of why TI does not recommend using $R_{\theta JC(top)}$ to determine thermal characteristics, see the [Using New Thermal Metrics application note](#), available for download at www.ti.com. For further information, see the [Semiconductor and IC Package Thermal Metrics application note](#), also available on the TI website.

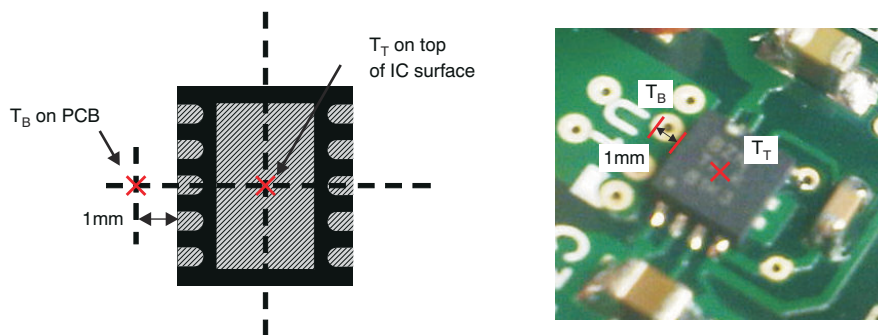


図 8-9. Measuring Points for T_T and T_B

8.4.2 Layout Example

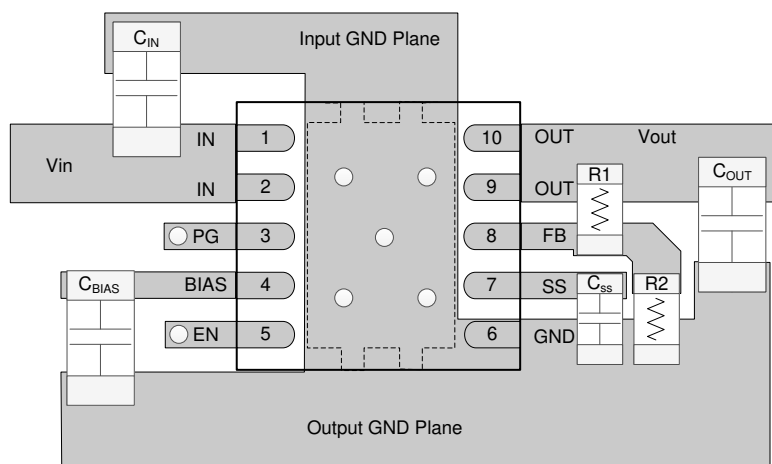


图 8-10. TPS547 Layout Recommendation

9 Device and Documentation Support

9.1 Device Support

9.1.1 Development Support

9.1.1.1 Evaluation Module

An evaluation module (EVM) is available to assist in the initial circuit performance evaluation using the TPS74701. The [TPS74701EVM-177 evaluation module](#) (and [related user guide](#)) can be requested at the Texas Instruments website through the product folders or purchased directly from the [TI eStore](#).

9.1.1.2 Spice Models

Computer simulation of circuit performance using SPICE is often useful when analyzing the performance of analog circuits and systems. A SPICE model for TPS74701 is available through the product folders under *Simulation Models*.

9.1.2 Device Nomenclature

表 9-1. Device Nomenclature⁽¹⁾

PRODUCT	V _{OUT} ⁽²⁾
TPS747xyyyz	xx is the nominal output voltage (for example, 12 = 1.2 V, 15 = 1.5 V, 01 = Adjustable). ⁽³⁾ YYY is the package designator. Z is the package quantity.

- (1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the device product folder on [www.ti.com](#).
 (2) Fixed output voltages from 0.8 V to 3.3 V are available; minimum order quantities may apply. Contact factory for details and availability.
 (3) For fixed 0.8-V operation, tie FB to OUT.

9.2 Documentation Support

9.2.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Using New Thermal Metrics application note](#)
- Texas Instruments, [Semiconductor and IC Package Thermal Metrics application note](#)

9.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](#) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

9.4 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の[使用条件](#)を参照してください。

9.5 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

9.6 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.7 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS74701DRCR	Active	Production	VSON (DRC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCR.A	Active	Production	VSON (DRC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCRG4	Active	Production	VSON (DRC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCRM3	Active	Production	VSON (DRC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCRM3.A	Active	Production	VSON (DRC) 10	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCT	Active	Production	VSON (DRC) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCT.A	Active	Production	VSON (DRC) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG
TPS74701DRCTG4	Active	Production	VSON (DRC) 10	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	CEG

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

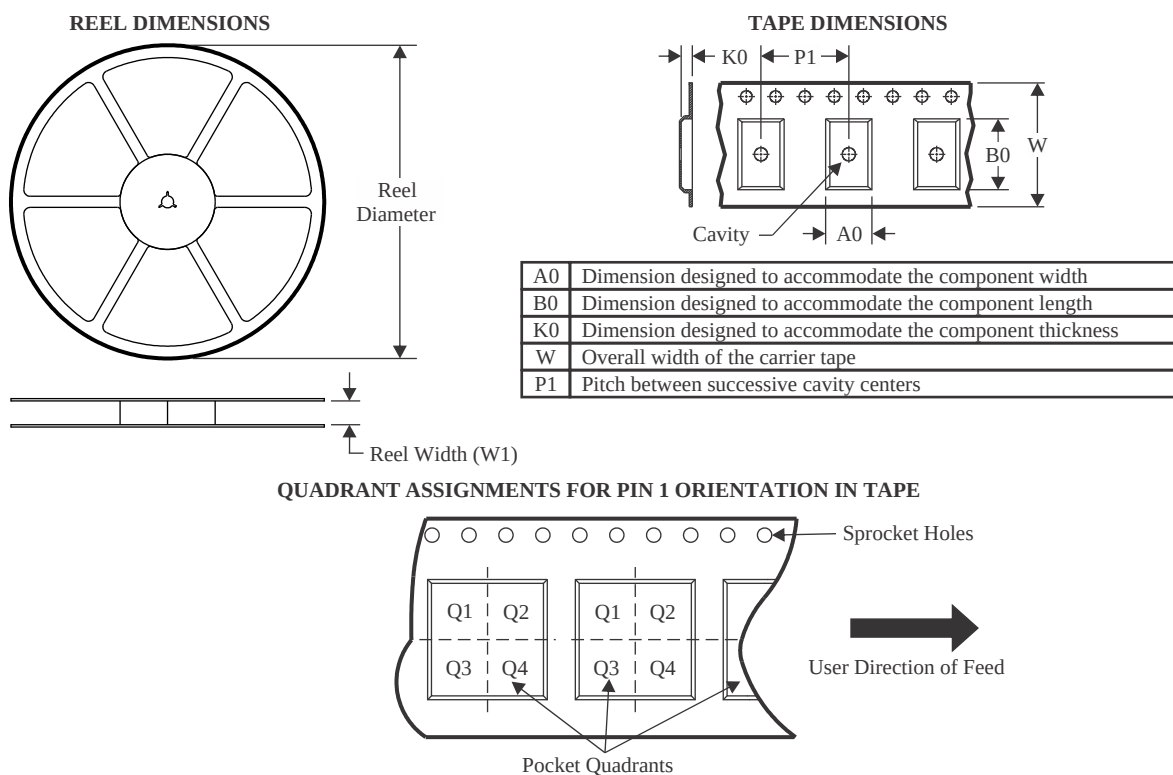
OTHER QUALIFIED VERSIONS OF TPS74701 :

- Automotive : [TPS74701-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

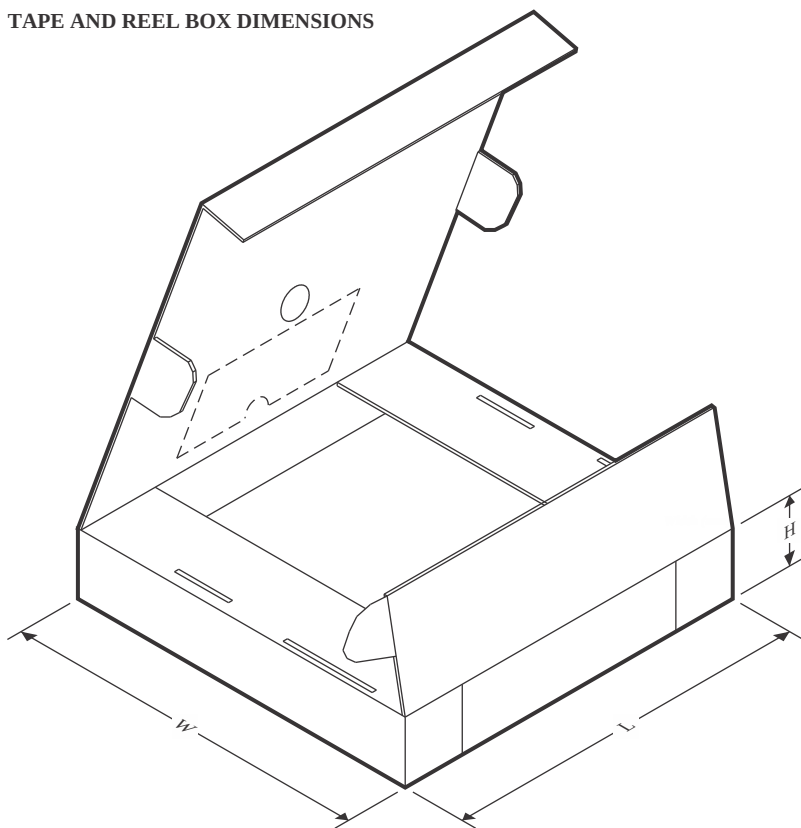
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS74701DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TPS74701DRCRM3	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TPS74701DRCT	VSON	DRC	10	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS74701DRCR	VSON	DRC	10	3000	360.0	360.0	36.0
TPS74701DRCRM3	VSON	DRC	10	3000	367.0	367.0	35.0
TPS74701DRCT	VSON	DRC	10	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

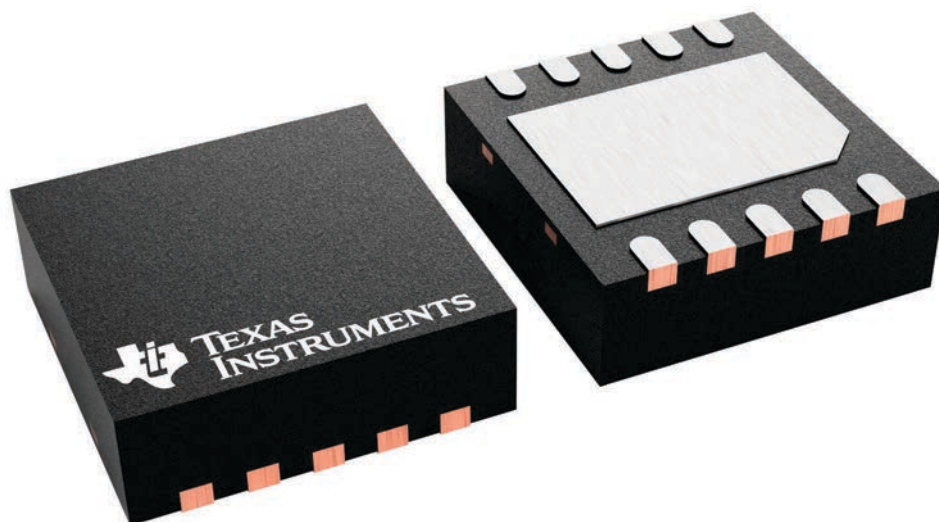
DRC 10

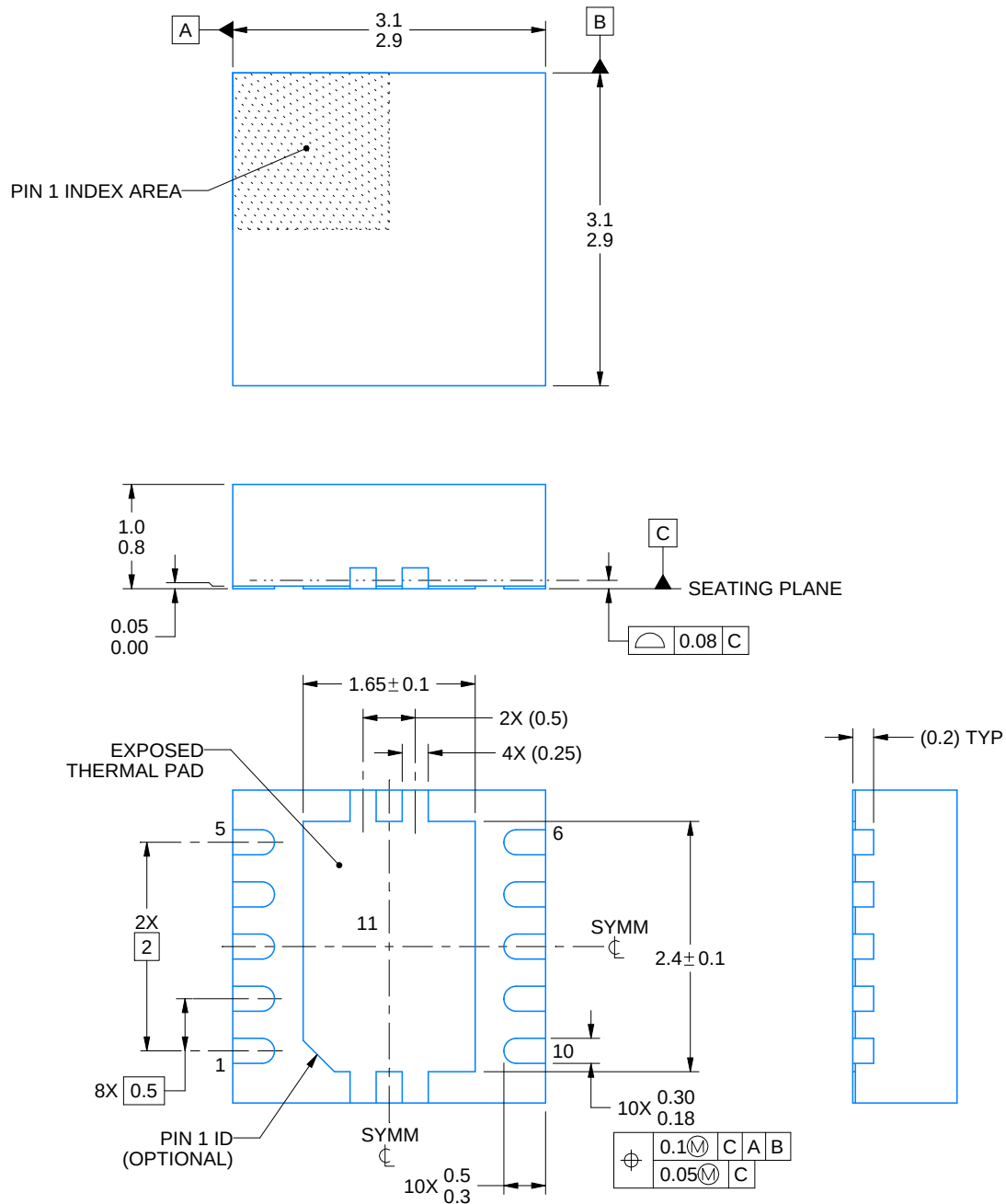
VSON - 1 mm max height

3 x 3, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.





4218878/B 07/2018

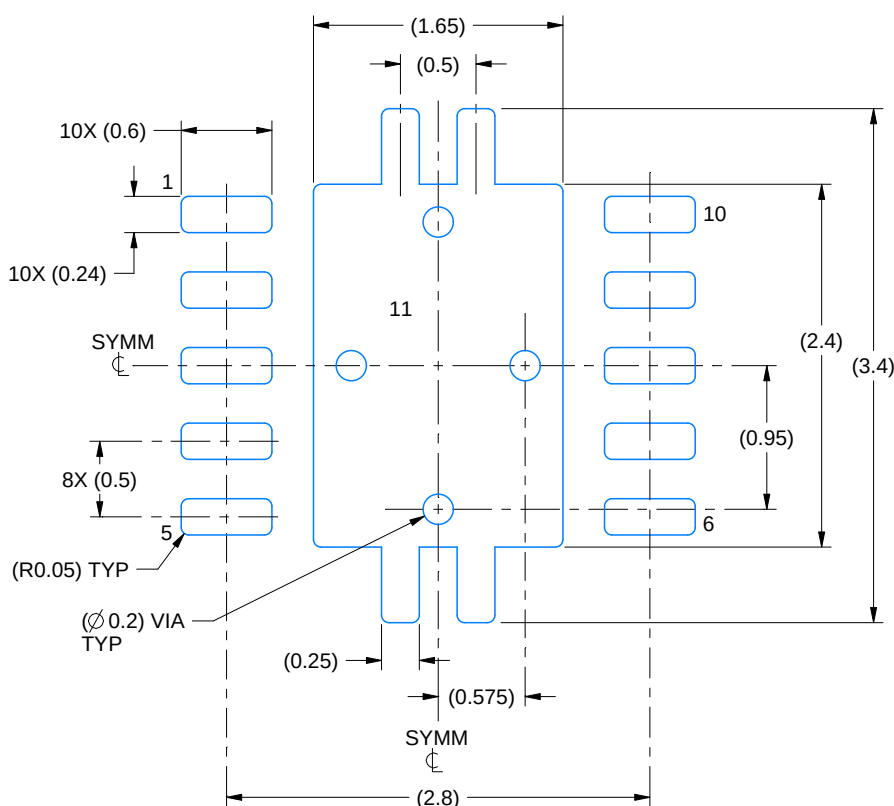
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

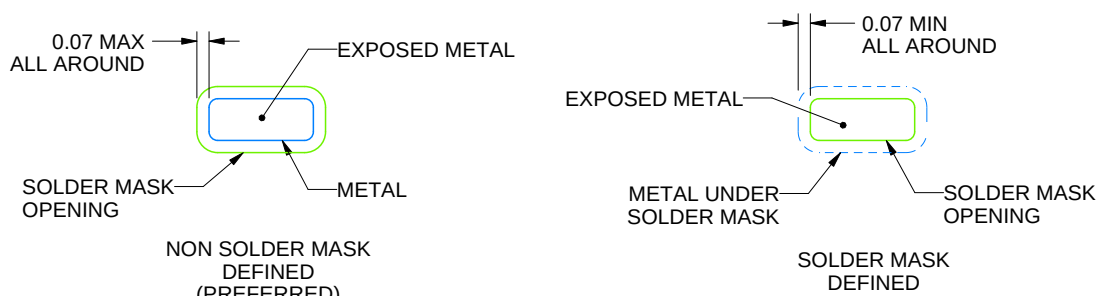
DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X



SOLDER MASK DETAILS

4218878/B 07/2018

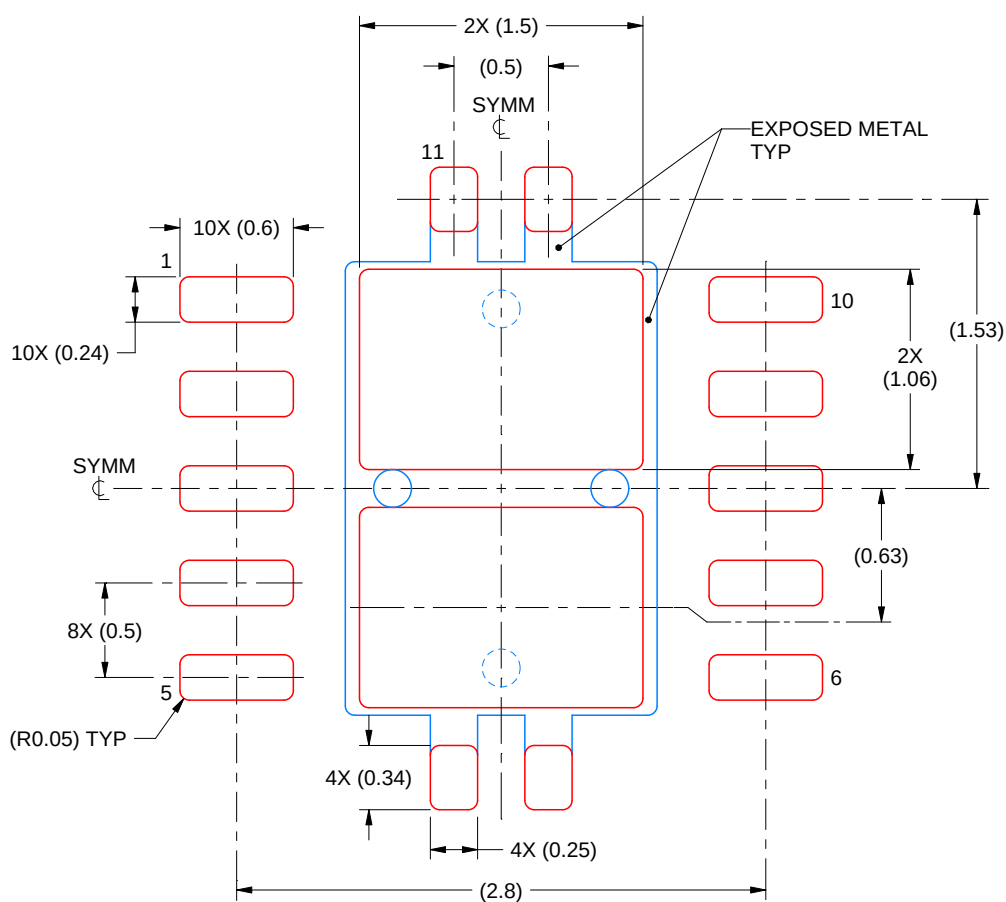
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:
80% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

4218878/B 07/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含みいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、TI は一切の責任を拒否します。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、[TI の総合的な品質ガイドライン](#)、[ti.com](https://www.ti.com) または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

Copyright © 2026, Texas Instruments Incorporated

最終更新日：2025 年 10 月